



Silicon enhancement mode nanostructures for quantum computing

Malcolm Carroll

Sandia National Laboratories
Albuquerque, New Mexico, USA

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LABORATORY DIRECTED RESEARCH & DEVELOPMENT

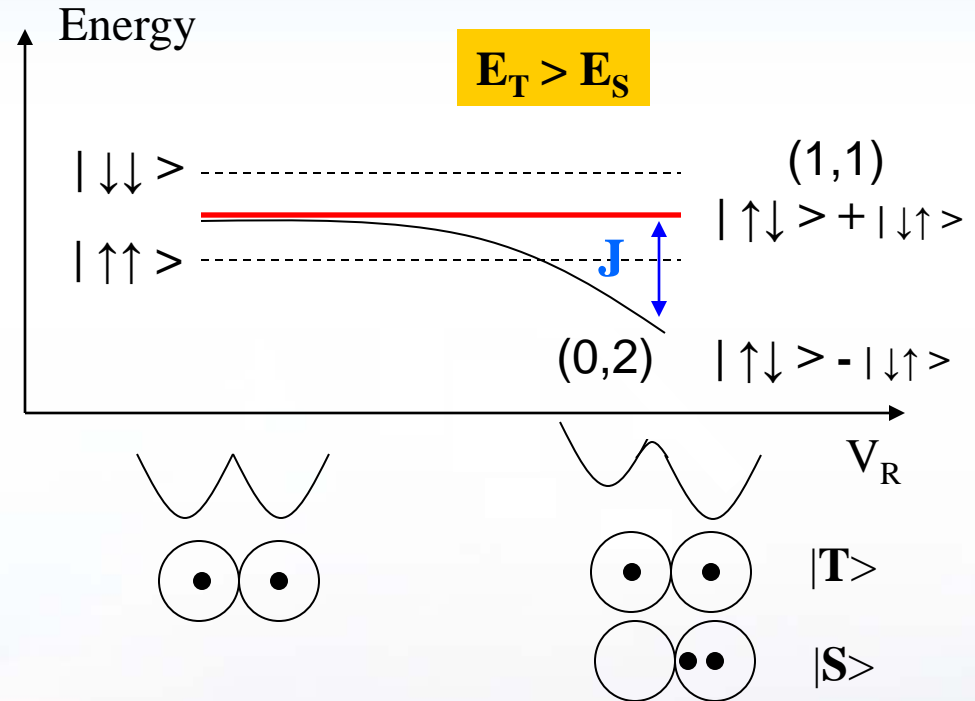
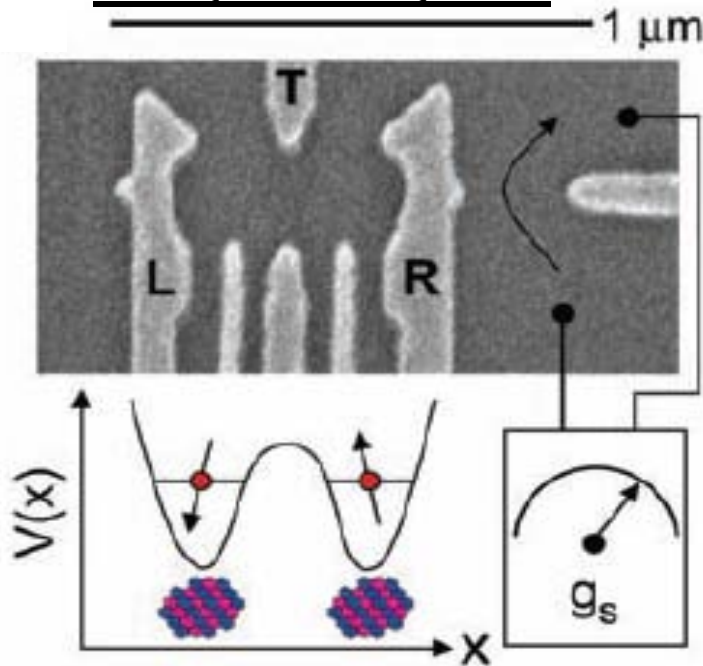
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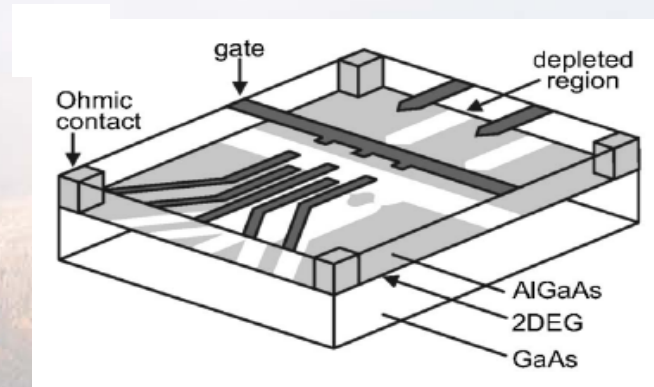
One inspiration for semiconductor quantum computing

Petta, Science, 2005



Elements:

- Two level system
 - $m=0$ subspace of 2 electrons
- Electrically tunable (tunnel coupling)
- Charge sense

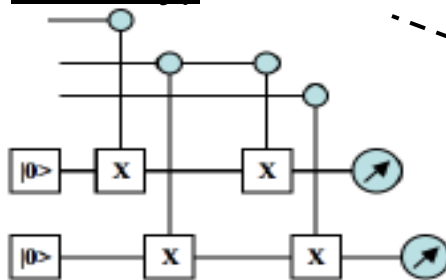


Quantum error correction needed for circuit model approach to QC

Some conclusions from logical memory

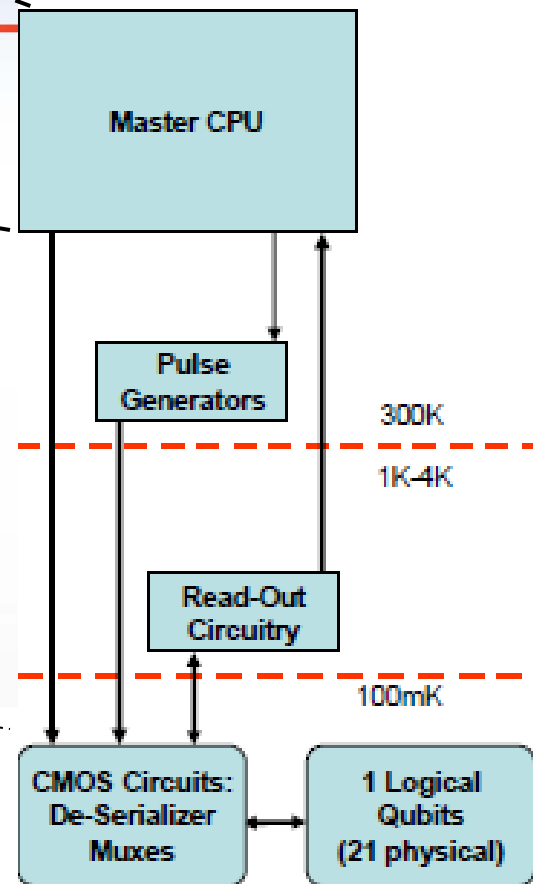
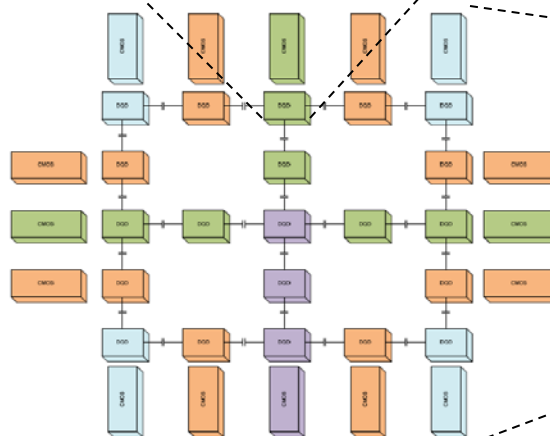
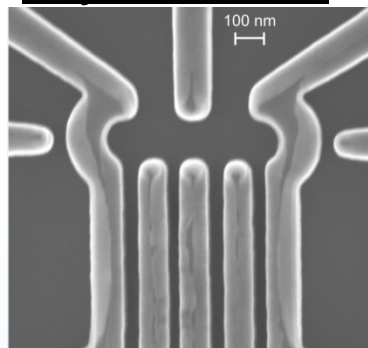
- Number of operations necessary to complete a QEC cycle => ballpark 10^{-4}
- Scheduling conflicts lead to more idles and gates (electronics, t_{msr} & DD)
- Circuit would show benefit at $p \sim 5 \times 10^{-4}$ assuming negligible idle error
- You want p/p_{th} as low as possible to reduce amount of QEC
- Fast high fidelity gates is made difficult in system (e.g., jitter on MUX/DEMUX clock)
- Long T_2 really helps both idle as well as minimizing error in gates w/out DCG

Quantum Circuit (Logical Memory)



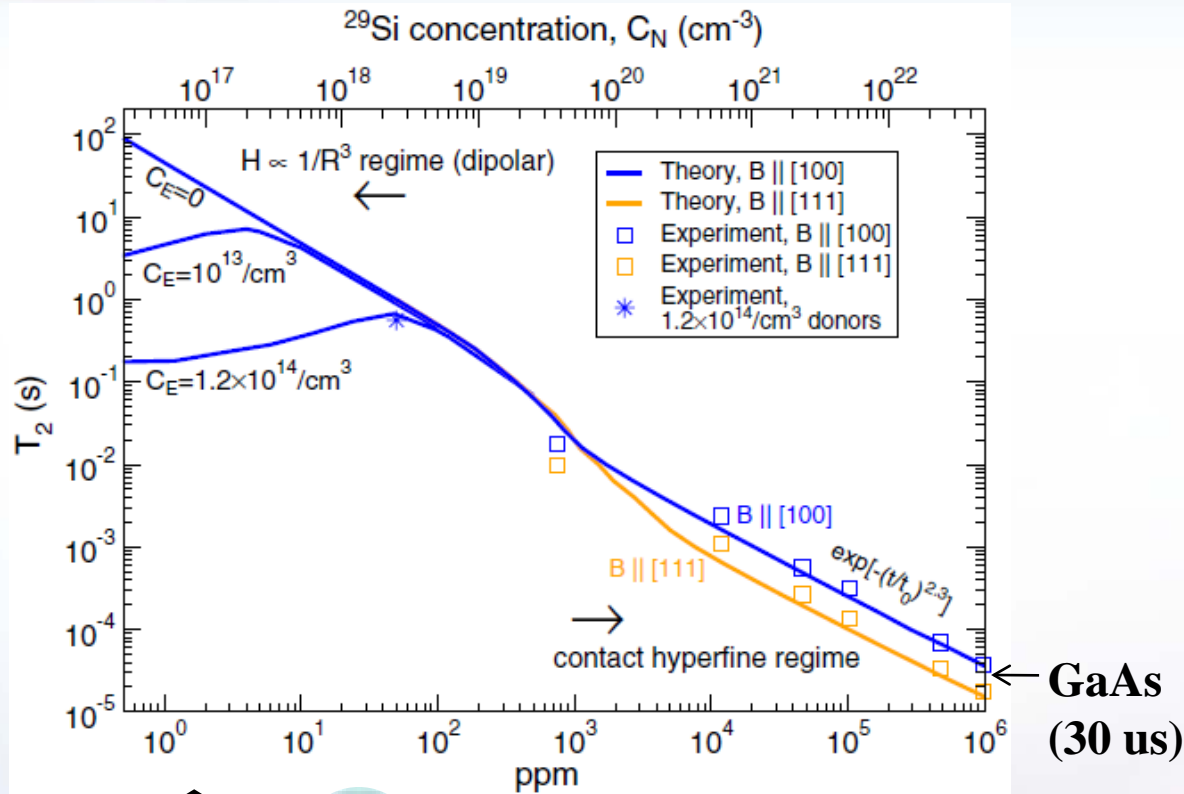
Classical-Quantum Interface

Physical Qubit

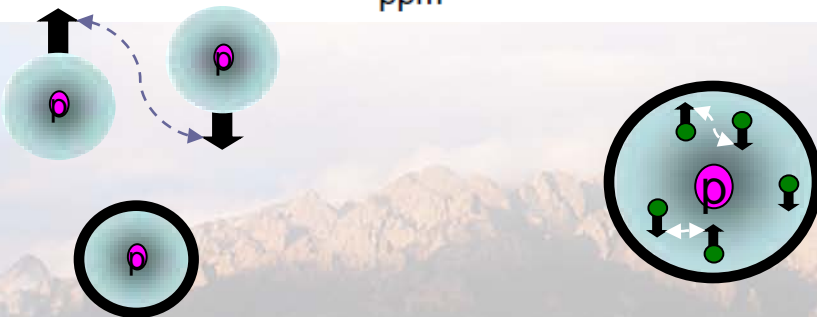


Chip Level Circuit (21 qubits)

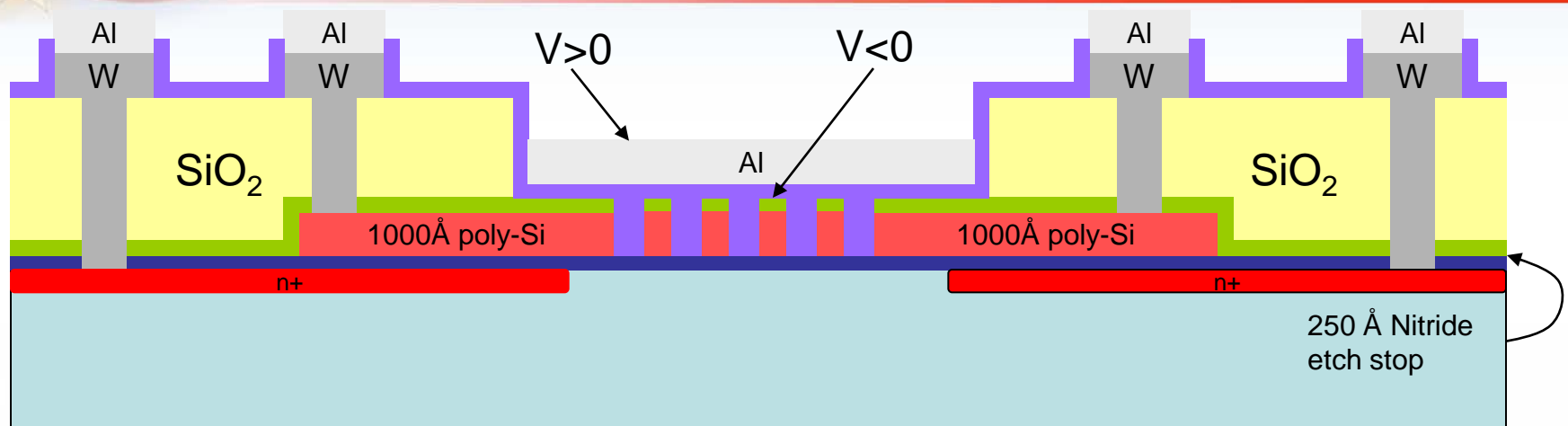
Motivation for Silicon Qubits



- GaAs has non-zero nuclear spin isotopes shorten T_2
- Si isotope enrichment removes nuclear spin, long T_2
- Nuclear spins can be useful for rotations between S & T0 but it limits T_2 , introduces errors on other gates
- Recent device progress in electron spin manipulation (spin read-out & evidence of coherence)
 - UNSW (donors)
 - UCLA (MOS)
 - HRL (SiGe mod. doped)
 - U. Wisconsin (SiGe mod. doped)



Silicon Enhancement Mode Quantum Dots

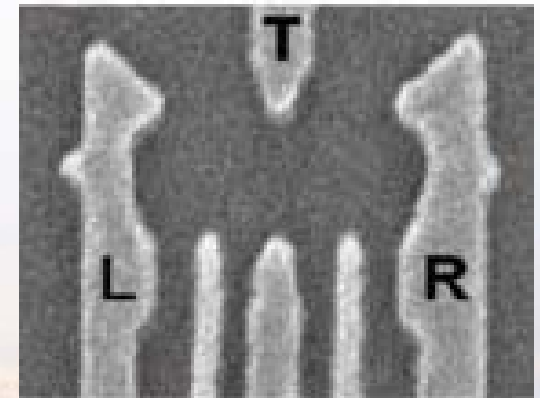


- Many silicon approaches
- SNL looking at enhancement mode & Si foundry approach
- This talk: MOS, SiGe/sSi and donors

Motivations

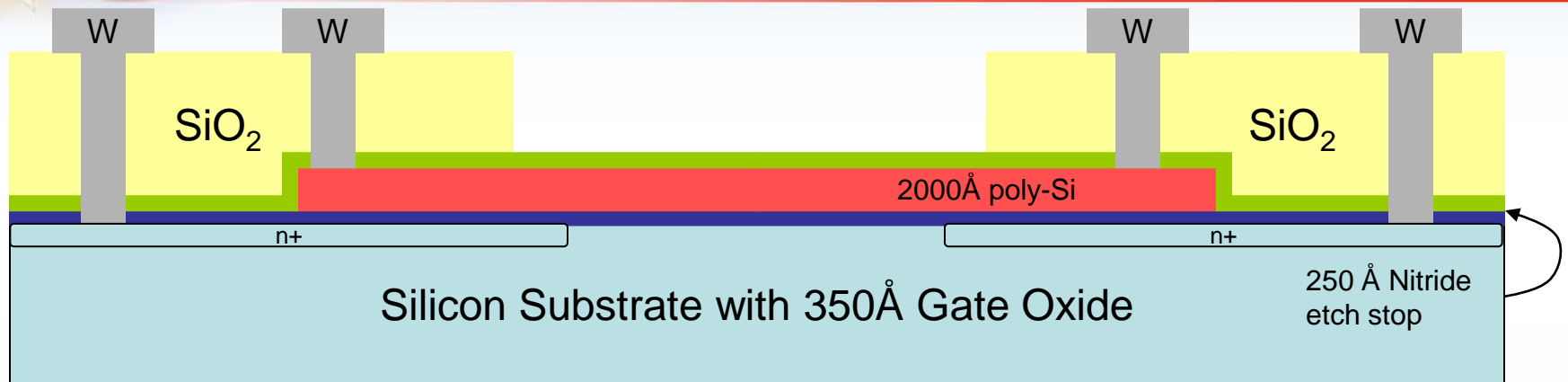
1. Platform is modular design for both donors and SiGe/sSi
2. Tunable parameters (density, valley splitting, g-factor?)
3. No dopants
4. Start with MOS:
 - well understood material system
 - overlapped interests for other Si approaches
5. CMOS compatible (MOS)

GaAs design to Si?



Petta et al. [2005]

Silicon foundry



MOS Stack from Si fab

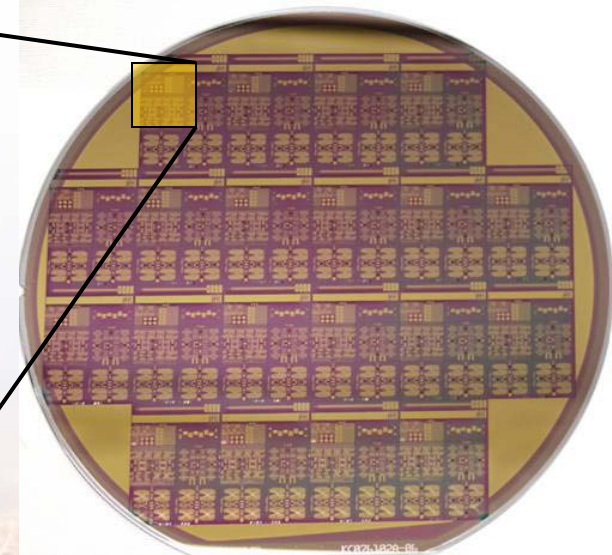
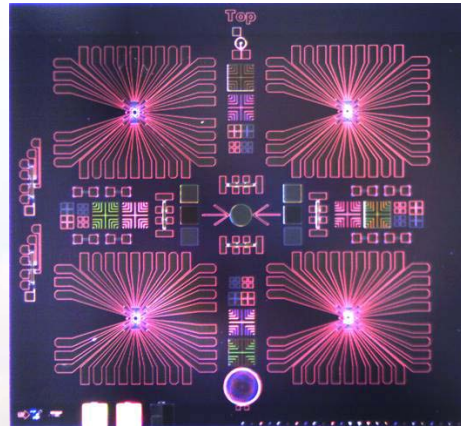
Deep UV lithography (0.18 μm)

7,500 – 15,000 mobility cm^2/Vs

QDs possible with 0.18 μm litho

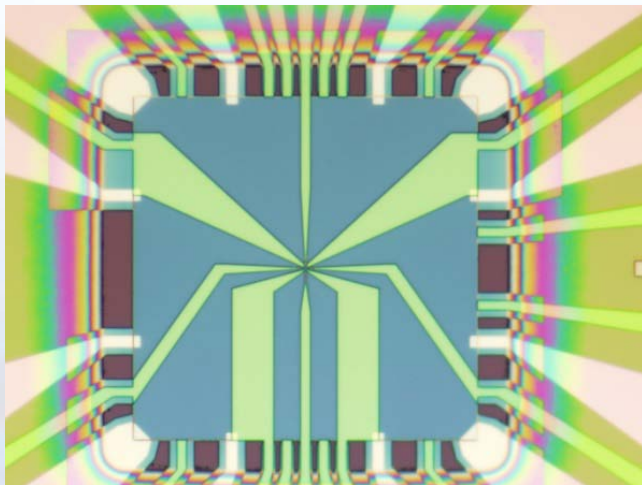
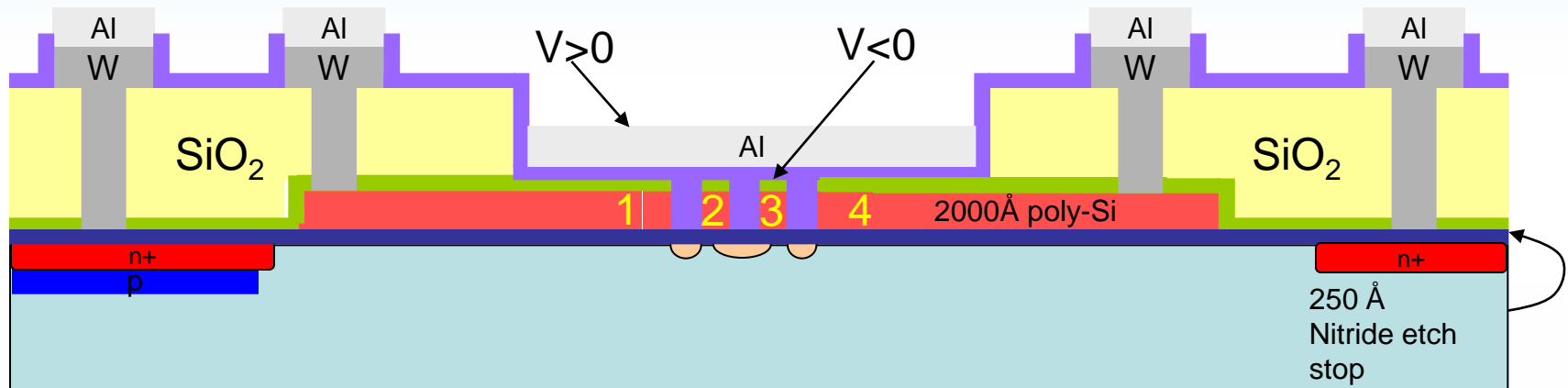
Smaller features w/ EBL in/out of fab

Standard MOS material set only





Back-end processing



Micro-fab facility

Rapid turn-around EBL

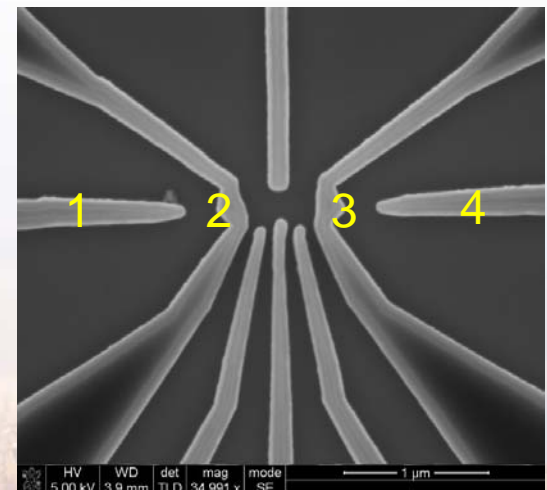
Poly-silicon etch

Aluminum oxide

Top AI gate

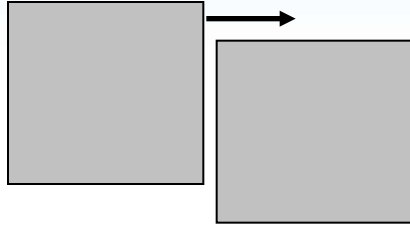
Low parasitic RF die

GaAs design to Si

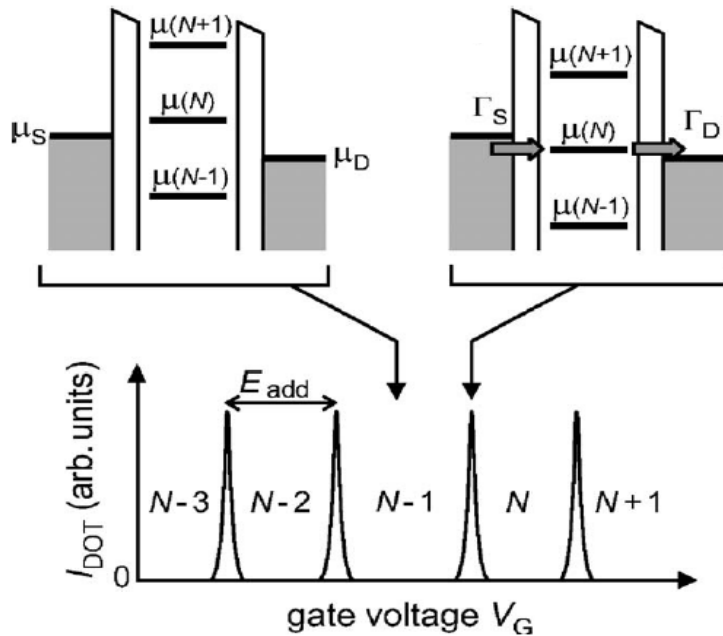


Coulomb blockade

Imbalance in chemical potential produces current



Current goes through QD when levels lines up

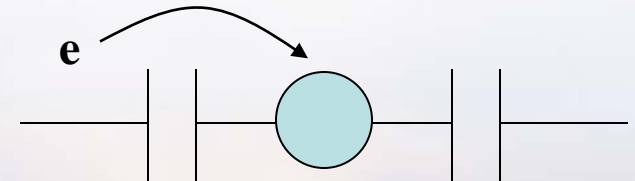


$$V = \frac{q}{C}$$

- Equally spaced energy levels related to charging energy of capacitance
- Periodic current resonances produces – “Coulomb blockade”
- Low temperatures required ($T \ll 4K$)

$$C_{\text{sum}} \sim 16 \text{ aF}$$

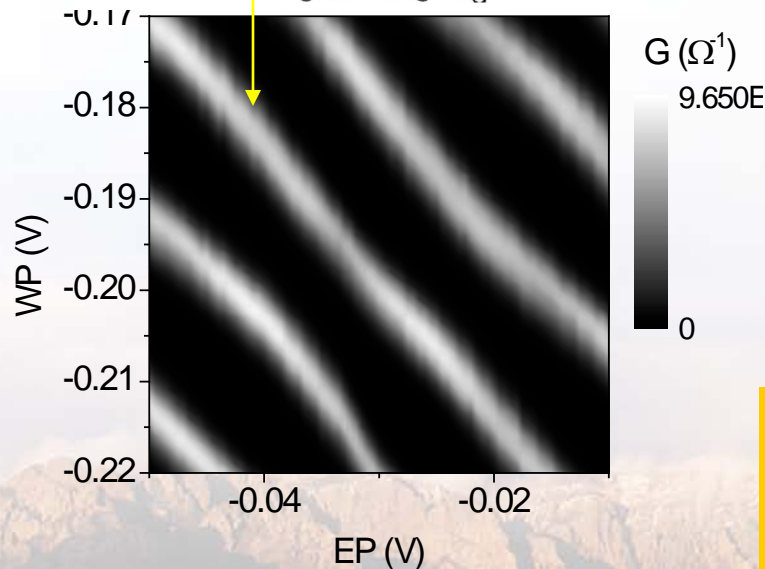
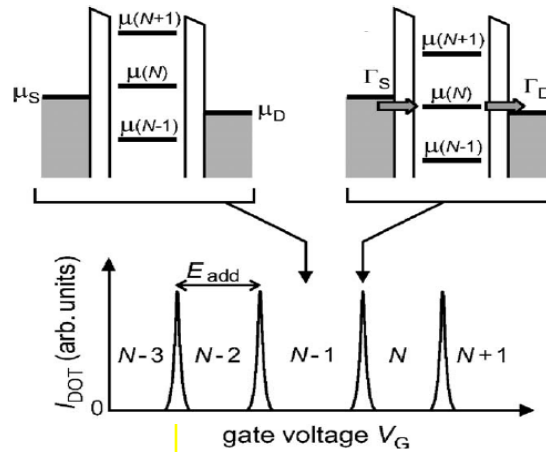
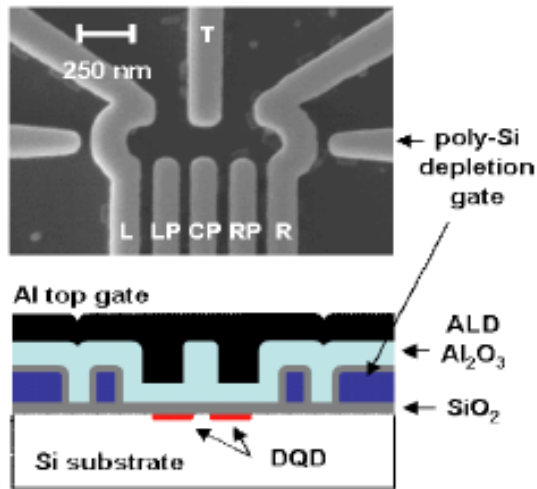
$$\Delta V = \frac{q}{C} \sim 1 \text{ mV}$$



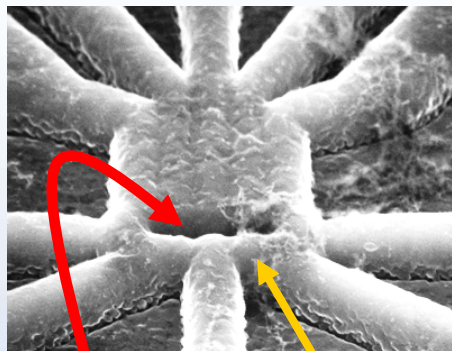
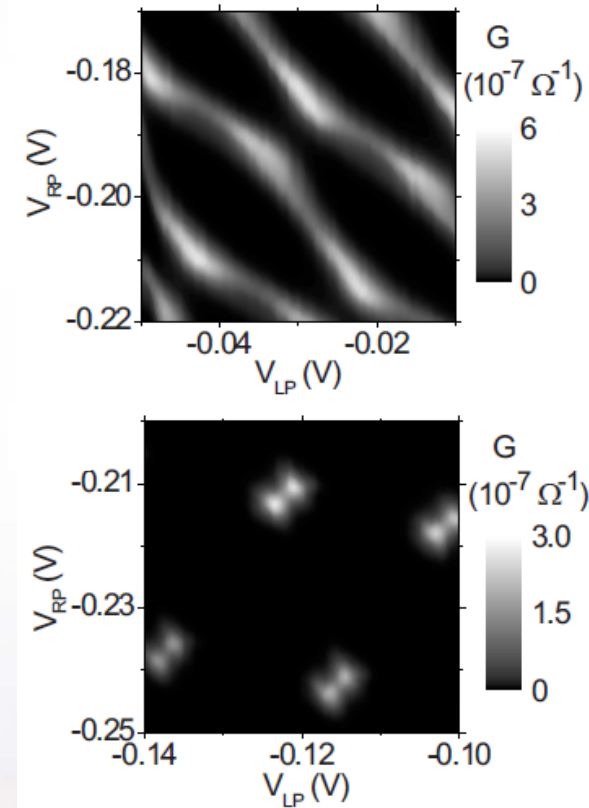
Chemical potential levels are spaced by charging energy

Reconfigurable Dot with Gates

Coulomb blockade



Tunability



$V_{\text{th-dot}}$

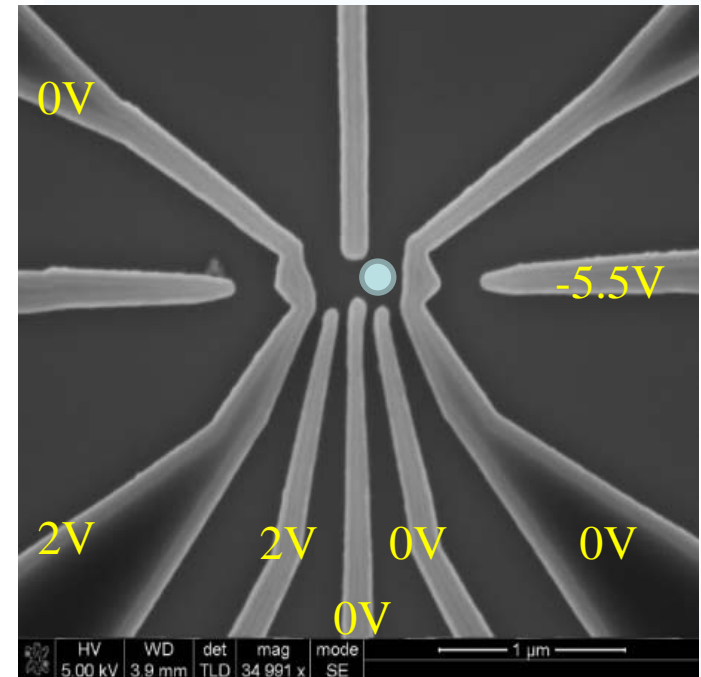
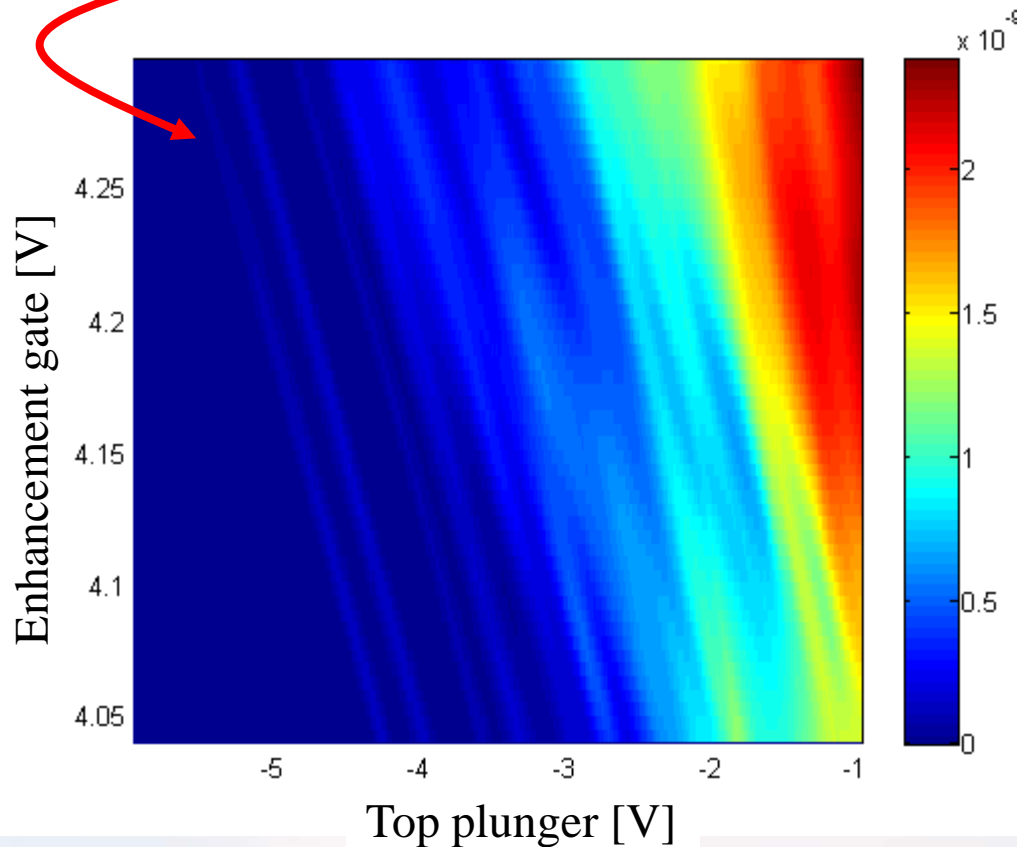
$V_{\text{th-barrier}}$

Problems:

1. Charge sensor constriction too thin
2. Top gate coupling imbalance to barrier/dot

Few electron single QD

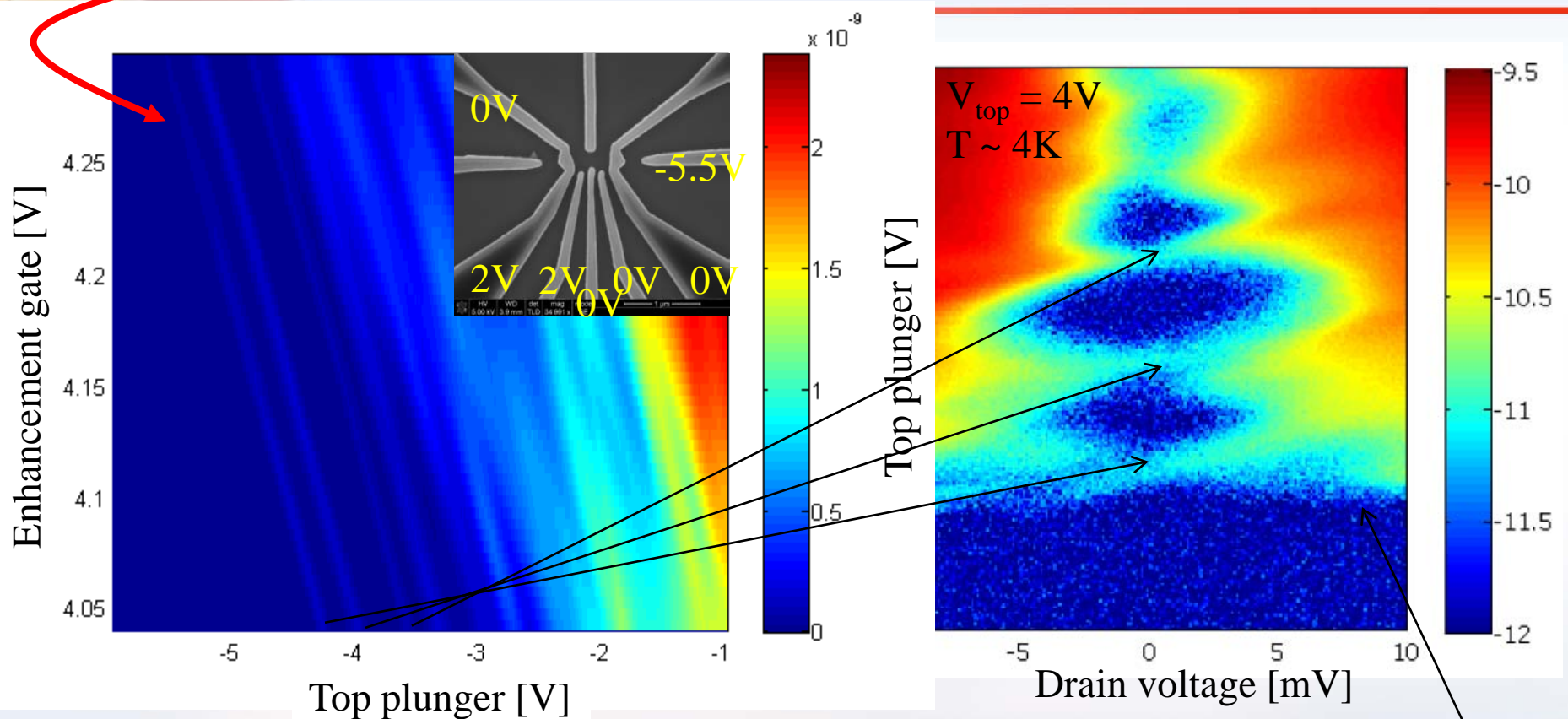
Last “visible” transition



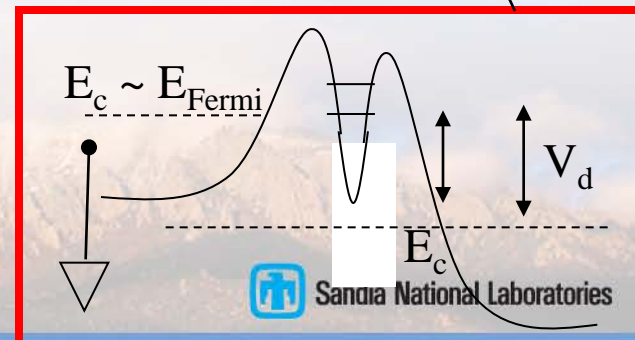
- Edge of transport through dot observed
- Several possible reasons
 - tunnel barrier is gradually turning off (often the case)
 - Last electron
- This case is not gradual and no additional transitions are observed over reasonably large V_{top} scan and V_{sd}

Wider tunnel barrier

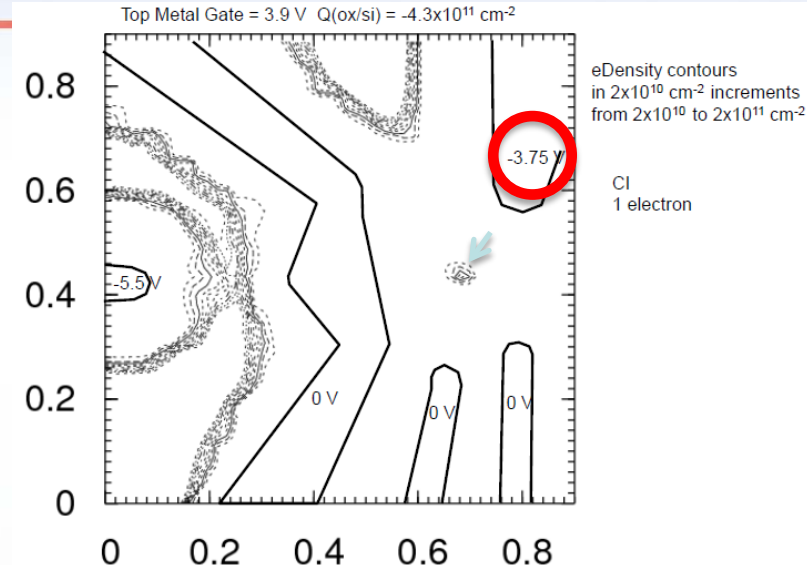
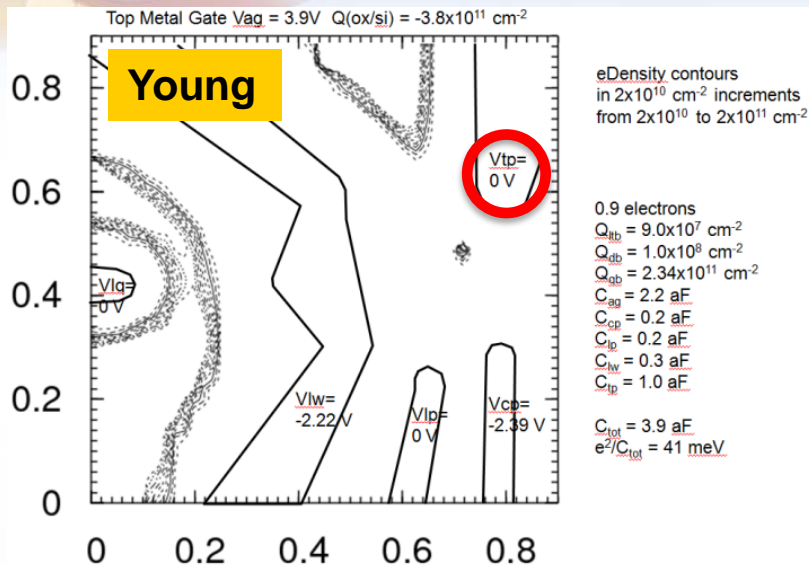
Last “visible” transition



- Edge of transport through dot observed
- Several possible reasons
 - tunnel barrier is gradually turning off (often the case)
 - Last electron
- This case is not gradual and no additional transitions are observed over reasonably large V_{top} scan and V_{sd}

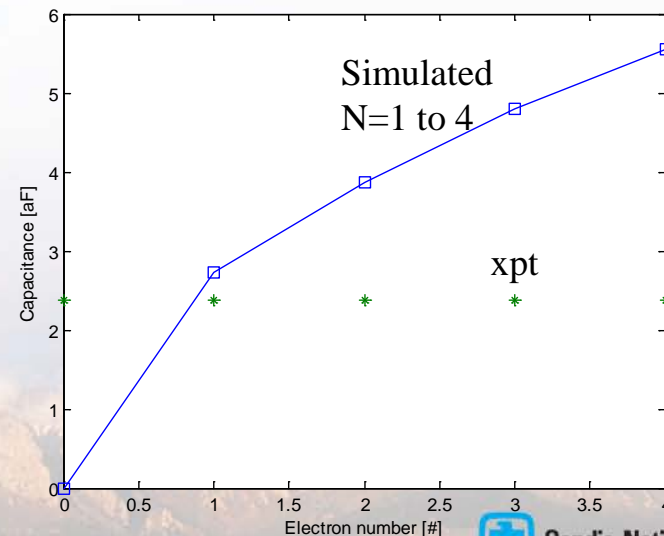


Simulation calibration



Gate	Measured [aF]	CI (N=1) [aF] TP=-3.75/ 0	Semi-classical [aF] TP=-3.75
AG	2.37	2.73 / 2.2	3.13
TP	0.48	0.29 / 1.0	0.3
L	0.56	1.56 / 0.3	1.9
LP	0.29	0.45 / 0.2	0.49
CP	0.54	0.59 / 0.2	0.66

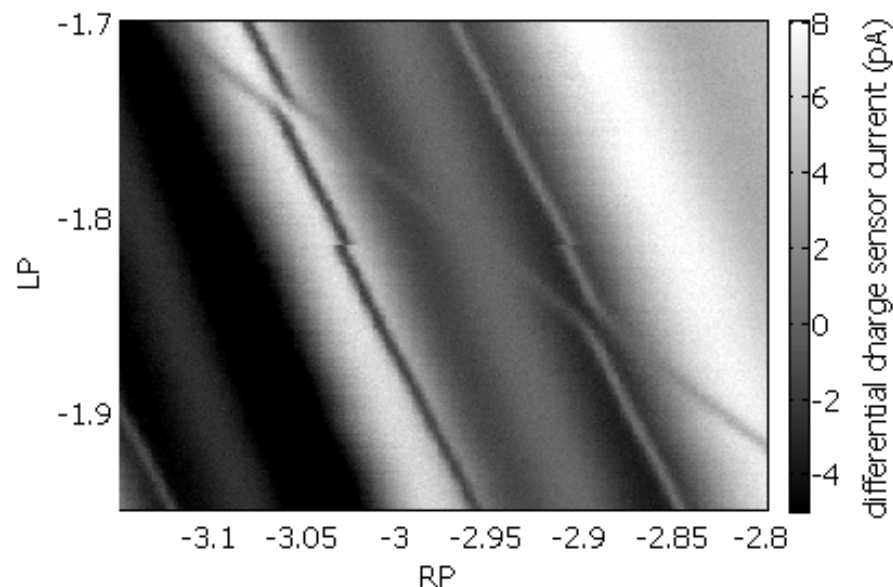
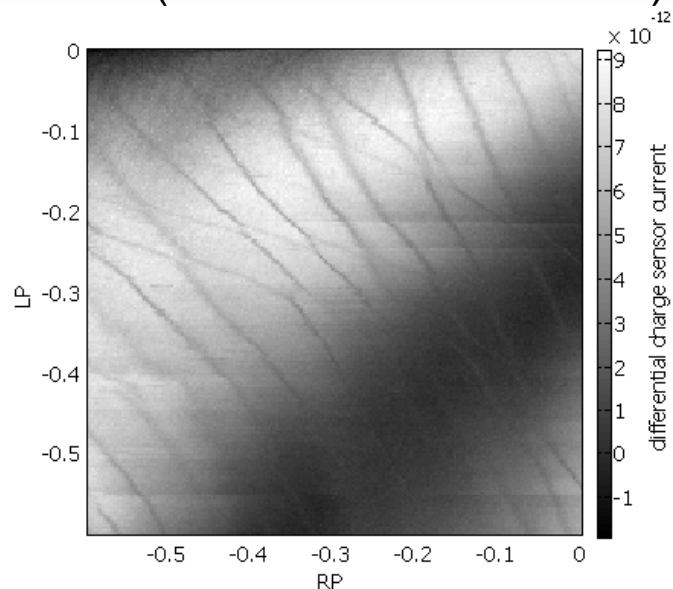
Carroll, Young



- Simulation is consistent with observed magnitudes in experiment at N=1

Double dot and charge sensing

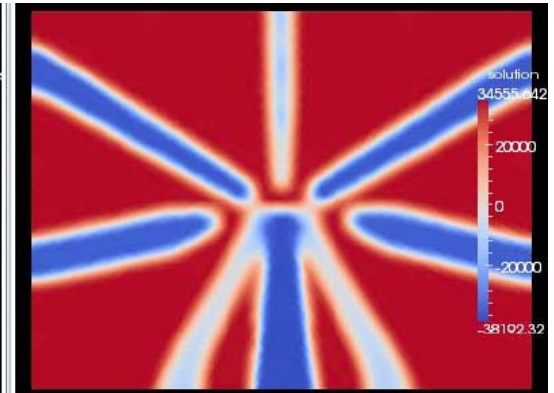
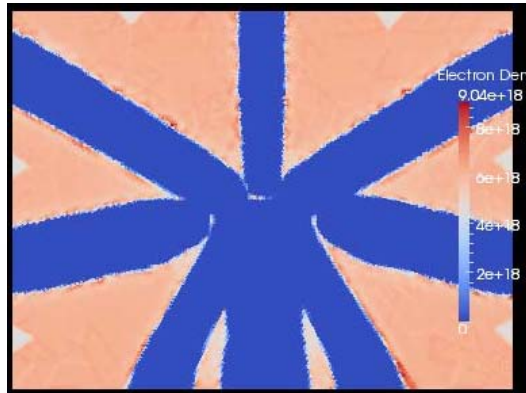
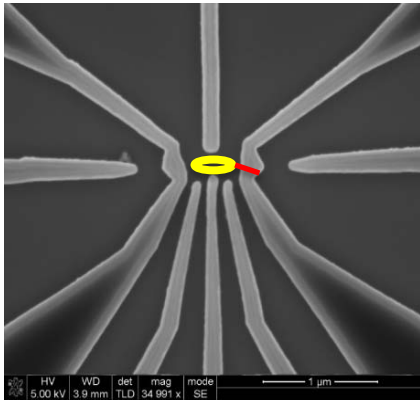
MOS (same device as before)



- Primary concern is to isolate a singlet and T0 subspace for qubit => tune DQDs
- Beginning to look for Pauli-blockade in many electron cases and few electron when possible
- Challenges:
 - Sensitivity
 - Reduce chance of defects
 - Fewer electrons
 - => smaller size designs

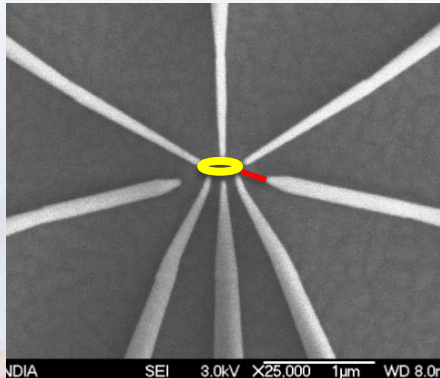
Smaller dot designs and path dependent tunability

Modeling optimization: few electron DQD possible

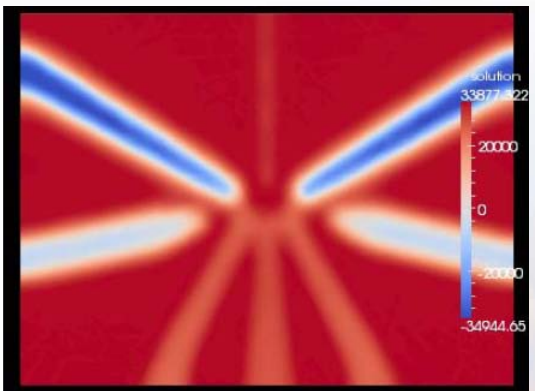
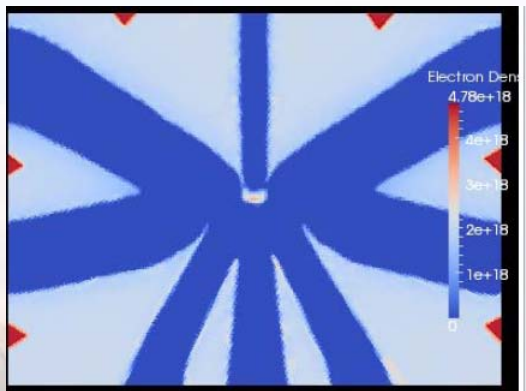


Smaller dot size & proximity

1. Better charge sensitivity
2. Fewer defects



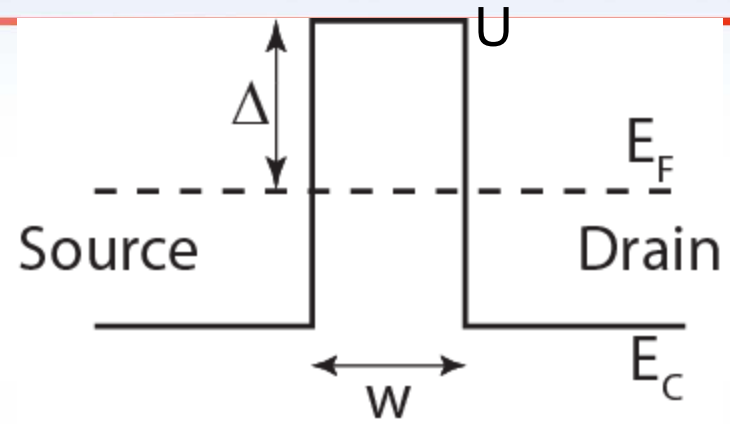
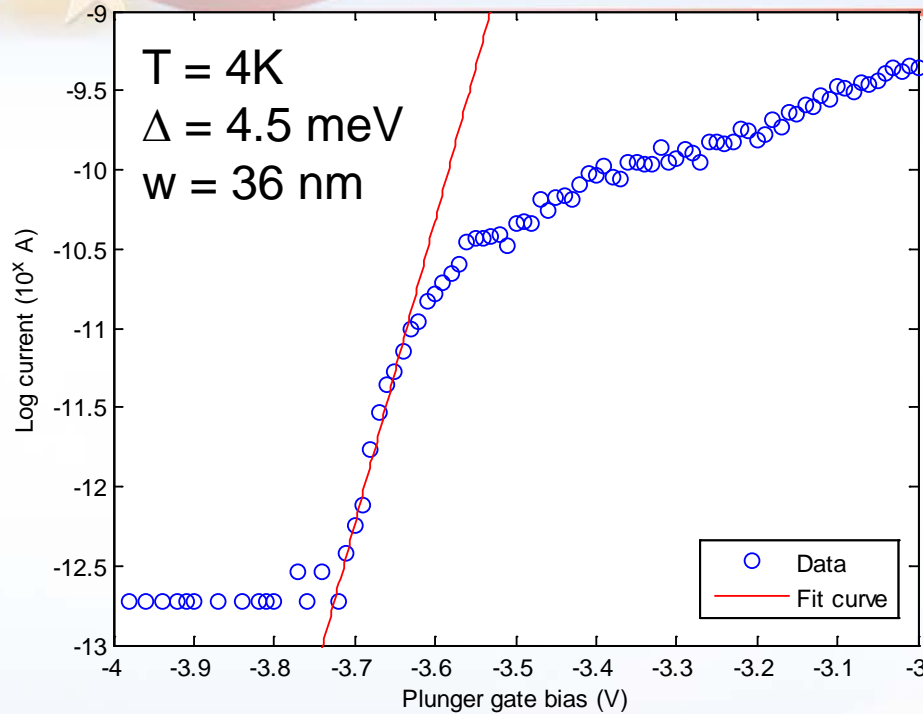
Modeling optimization: experimental path has non-ideal minima



Nielsen, Muller, Young (synergistic research)

Tunnel barrier model

$V_{dc} = 0.040$ mV, $D = 0.0045$ eV, $w = 3.58 \times 10^{-8}$ m



Limitations

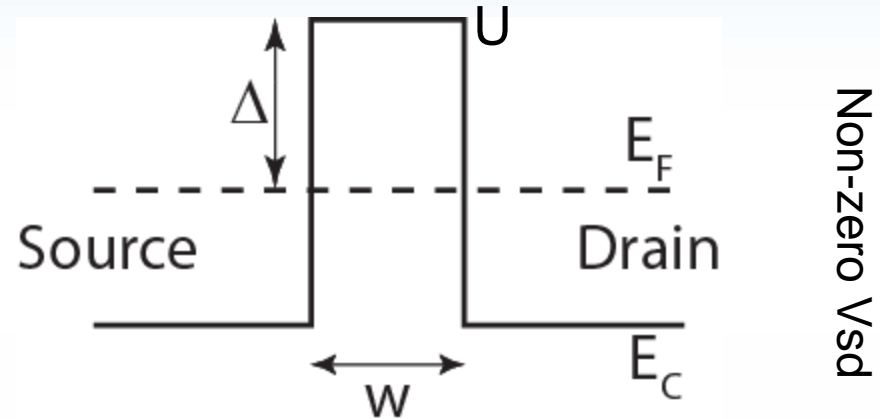
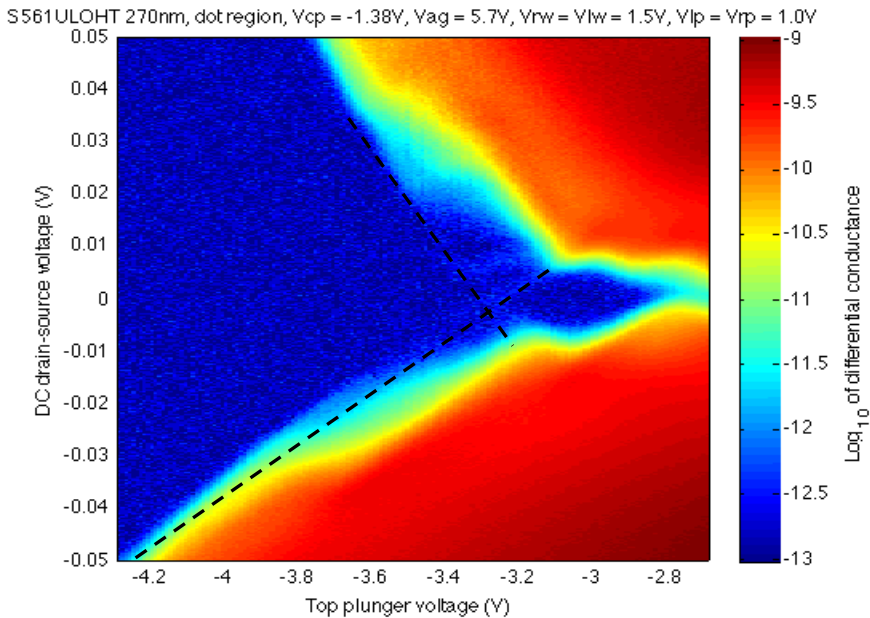
- Square barrier
- WKB approximation
- Linearize the radical
- Phenomenological parameter f_0

$$I = q\Gamma \approx f_0 e^{-\frac{2w}{\hbar} \sqrt{2m^* \Delta}}$$

$$\ln(I) = \ln(qf_0) - \frac{w}{\hbar} \sqrt{\frac{2m^*}{\Delta}} \left(2\Delta + q \frac{C_{gate}}{C_{\Sigma}} (V_0 - V) \right)$$

$$y = mx + b$$

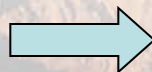
Consistent results



V_{ds} (mV)	V_g (V)	Δ (meV)	W (nm)	$\Delta@$ $V_{ds} = 0V$ $V_g = -3.4V$ (meV)
-11	-3.26	4.63	21.9	15.6
-10	-3.24	4.42	22.9	13.7
10	-3.12	2.79	26.8	13.8
11	-3.13	2.69	26.7	13.7

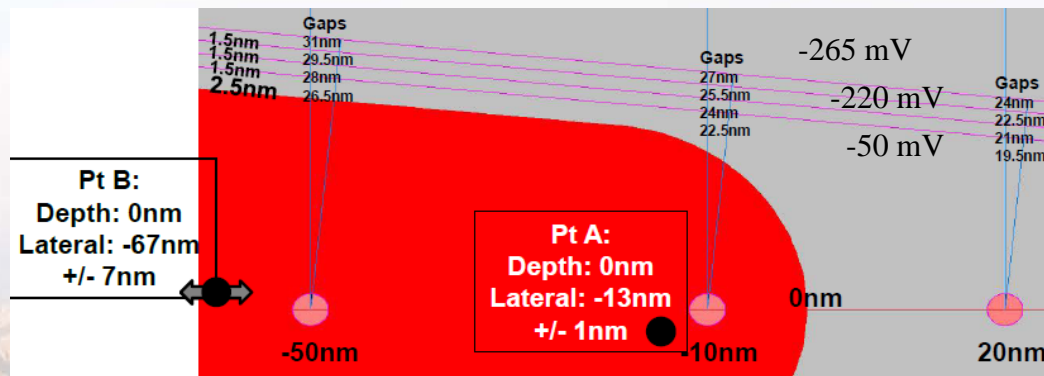
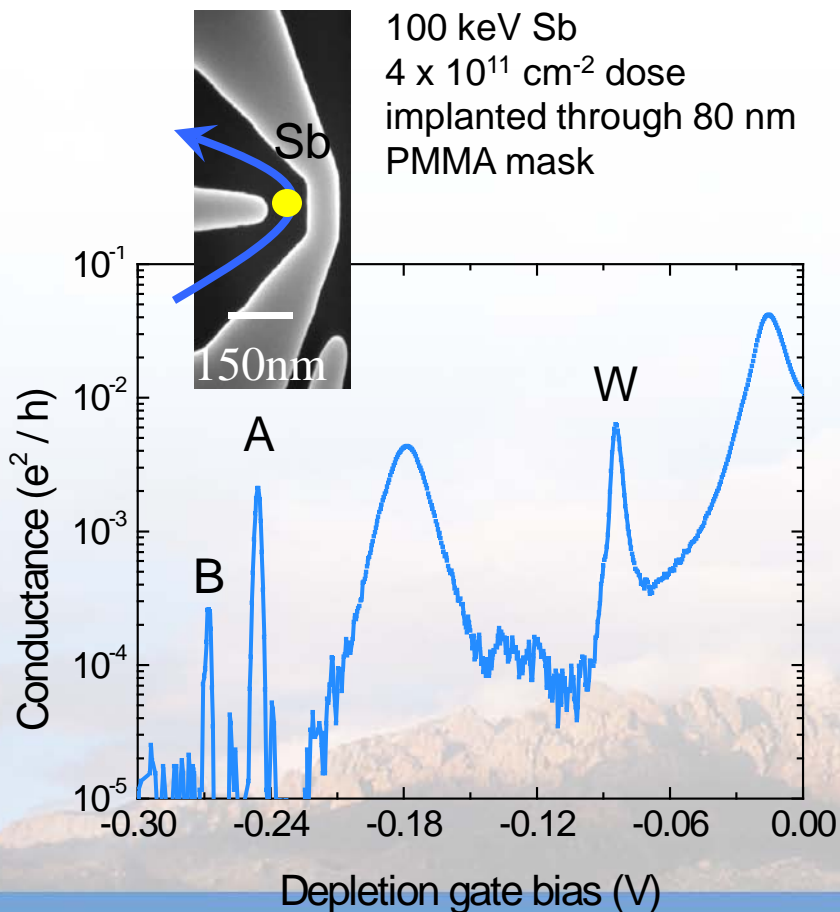
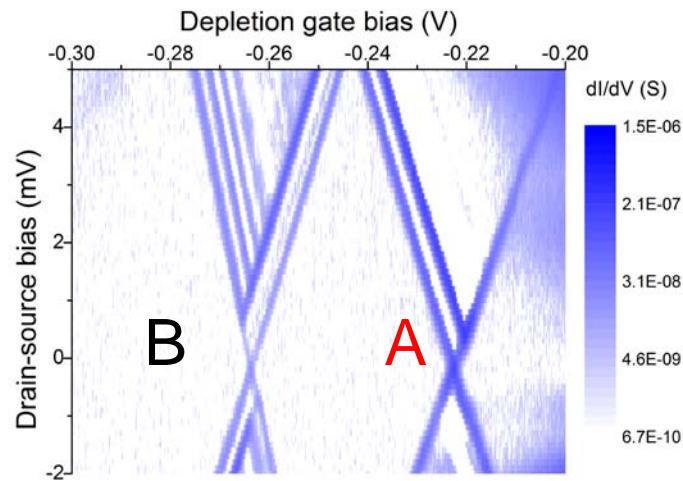
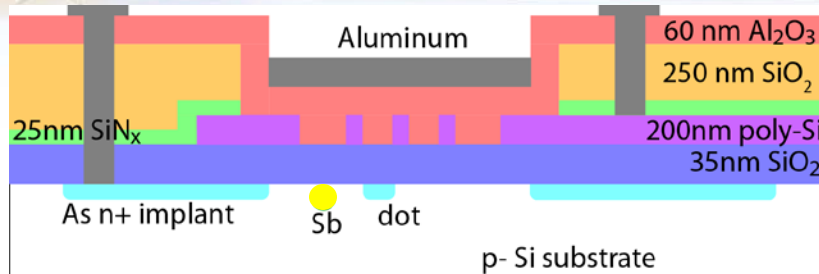
$$dU = \frac{\partial U}{\partial V_{sd}} dV_{sd} + \frac{\partial U}{\partial V_{gate}} dV_{gate}$$

$$dU = \Delta - \Delta_0 - q|V_{sd}|$$



$$\Delta = \Delta_0 + q|V_{sd}| + \frac{C_s}{C_\Sigma} dV_{sd} + \frac{C_g}{C_\Sigma} dV_{gate}$$

Triangulation of resonances in implanted split-gates



Comparison of tunnel barrier model to triangulation

Resonance B

Vsd (mV)	Vg (V)	Δ (meV)	W (nm)
25	-0.3805	2.21	48.4
22	-0.3745	2.53	45.6

Resonance A

Vsd (mV)	Vg (V)	Δ (meV)	W (nm)
25	-0.353	1.65	39.1
22	-0.345	1.82	38.6

For $V_{SD} = 0V$ and $V_g = -0.27V$, $\Delta = 9.12$ meV

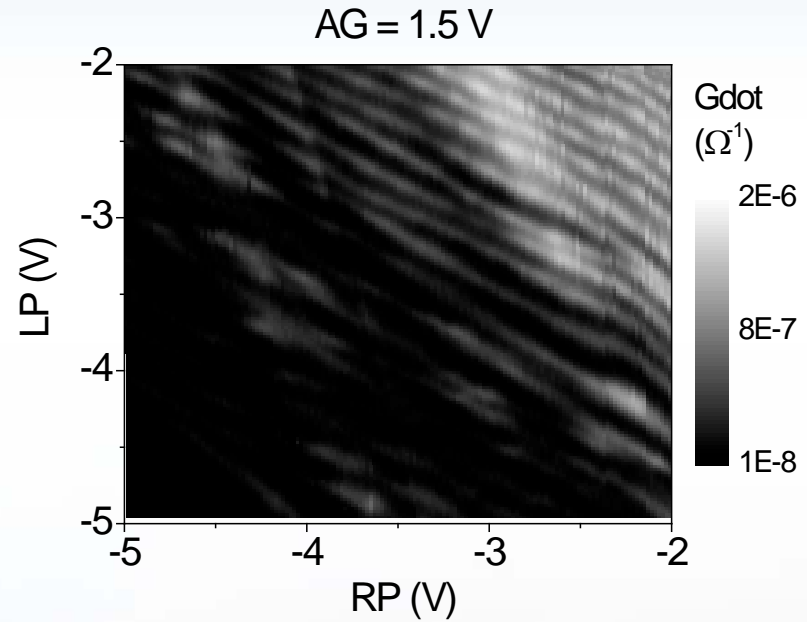
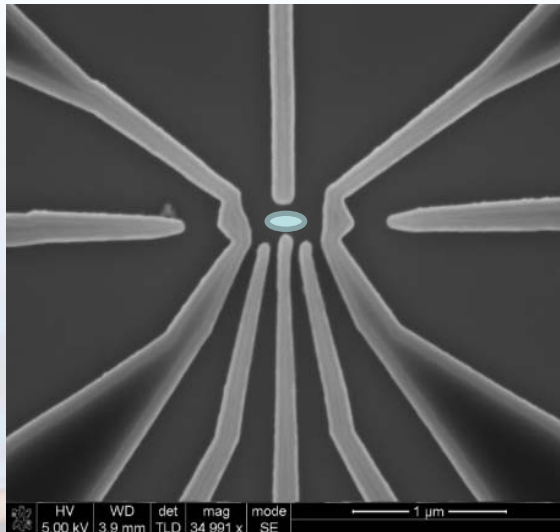
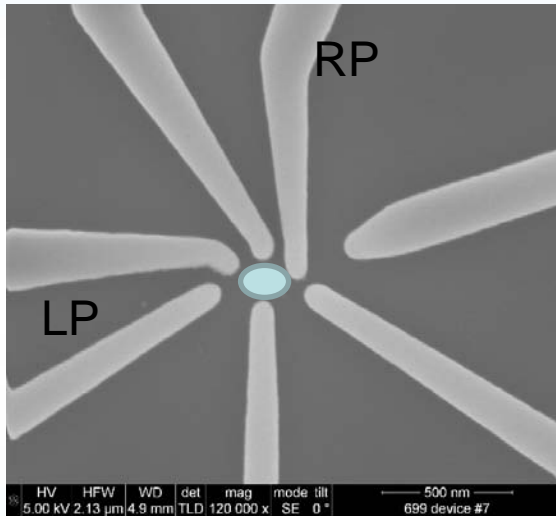
$dU/dV_{SD} = -0.4203$ eV/V ($C_s/C = 0.4468$)

For $V_{SD} = 0V$ and $V_g = -0.24V$, $\Delta = 6.05$ meV

$dU/dV_{SD} = -0.3825$ eV/V ($C_s/C = 0.3899$)

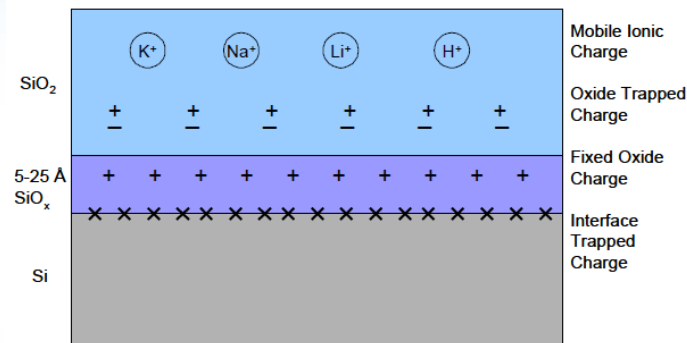
Method	Width (A) [nm]	Width (B) [nm]
Triangulation to $1.5 \times 10^{11} \text{ cm}^{-2}$ edge	29	34
Square barrier	39	46.5

Smaller design

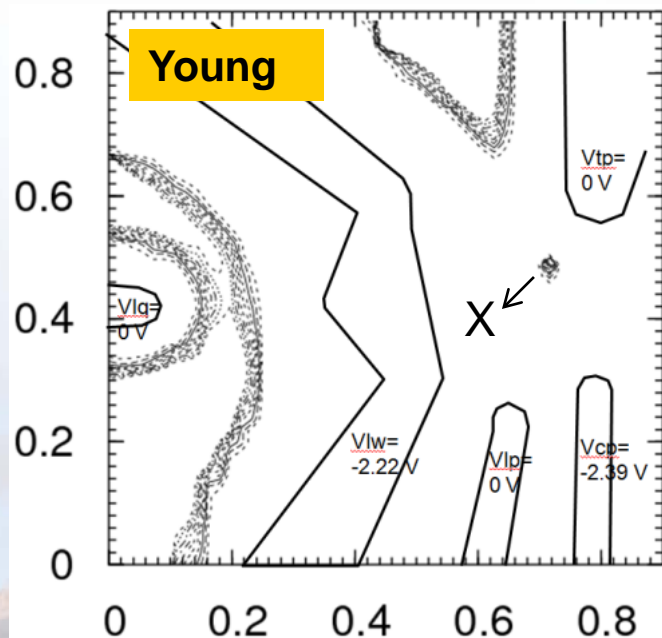


Persisting doubt about MOS DQDs for qubits

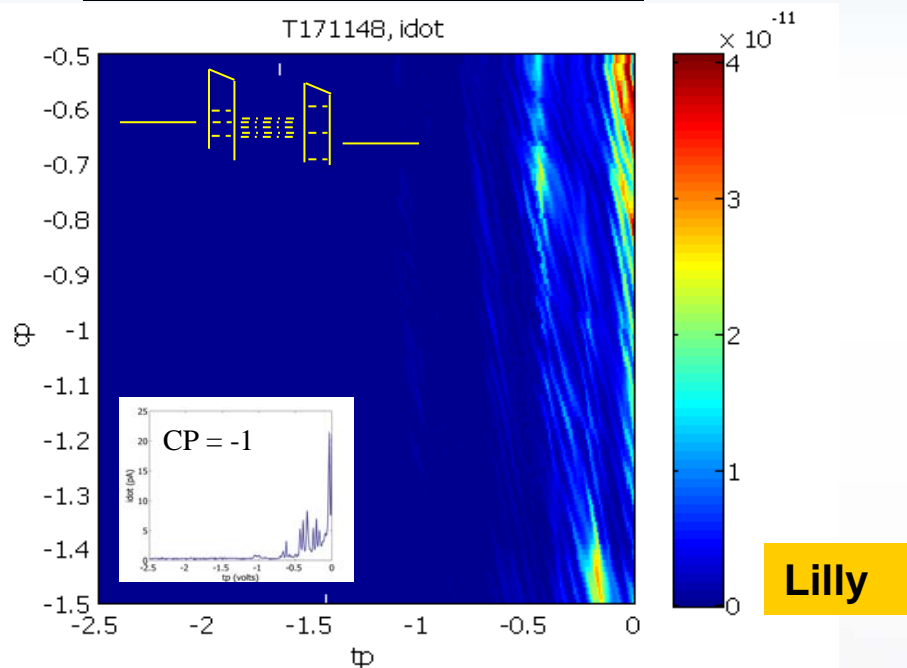
Defects



Uncontrolled localization



Coulomb blockade with disorder



Assume: DQD Area $\sim 100\text{ nm} \times 25\text{ nm}$

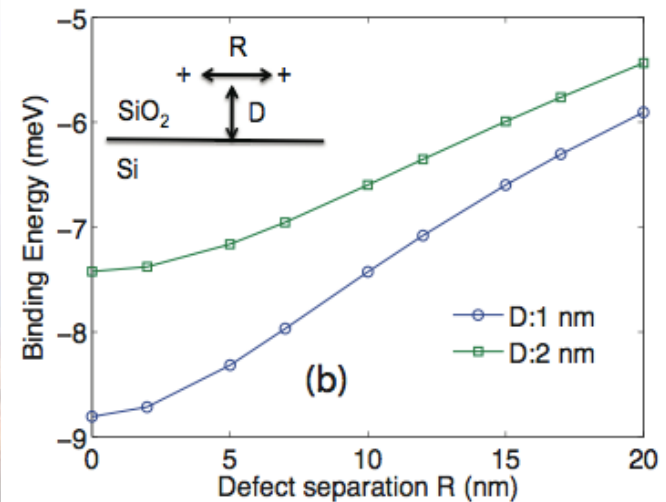
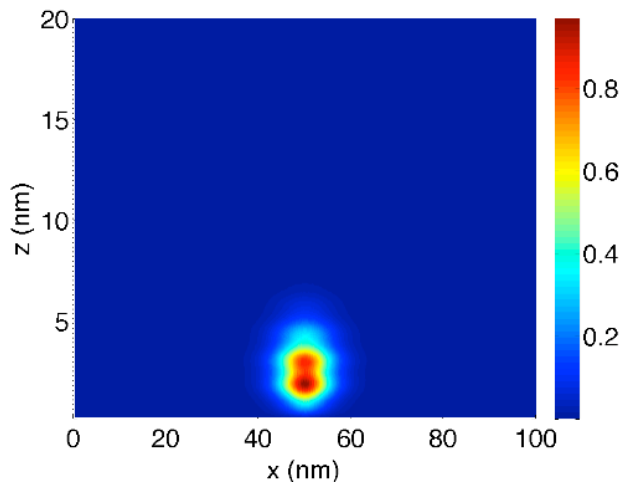
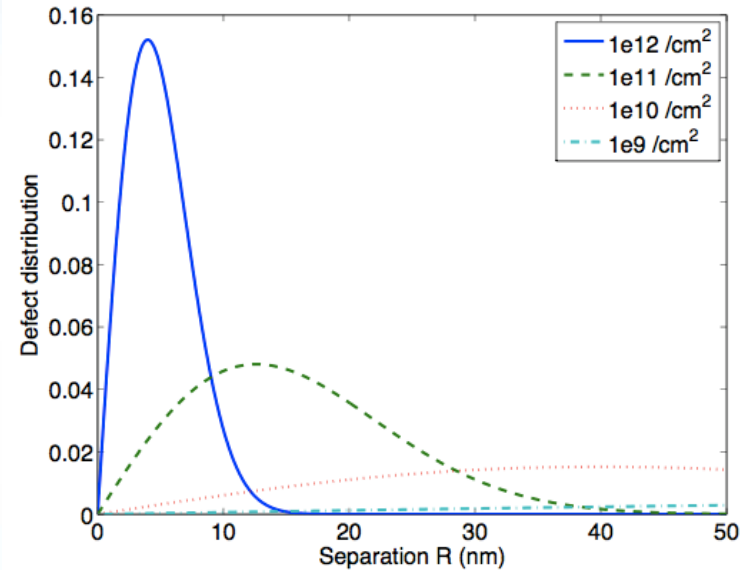
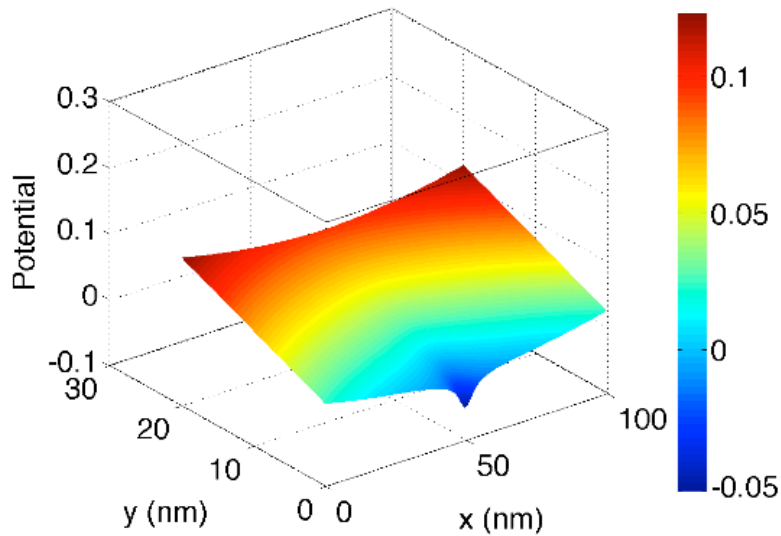
Number of defects in DQD area

$1 \times 10^{10} \rightarrow 0.25\text{ per QD}$

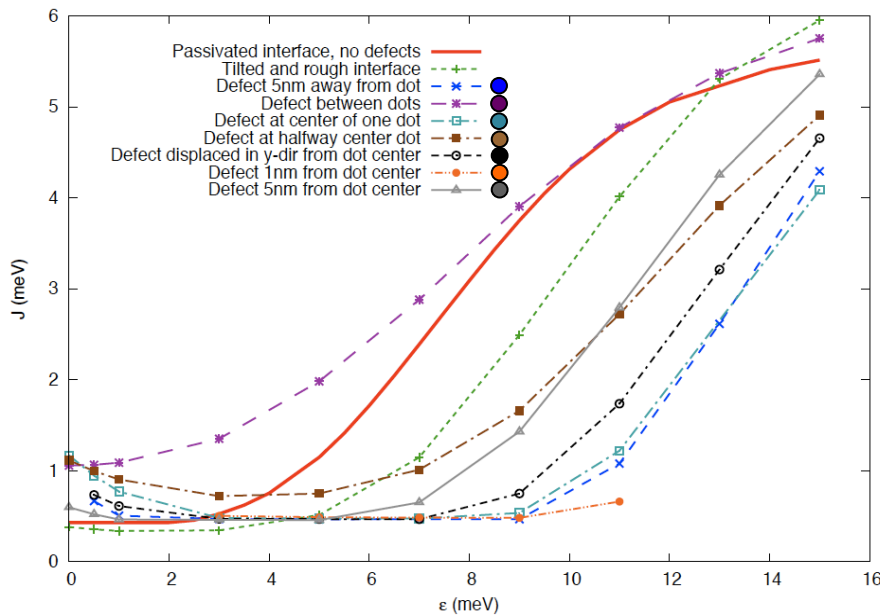
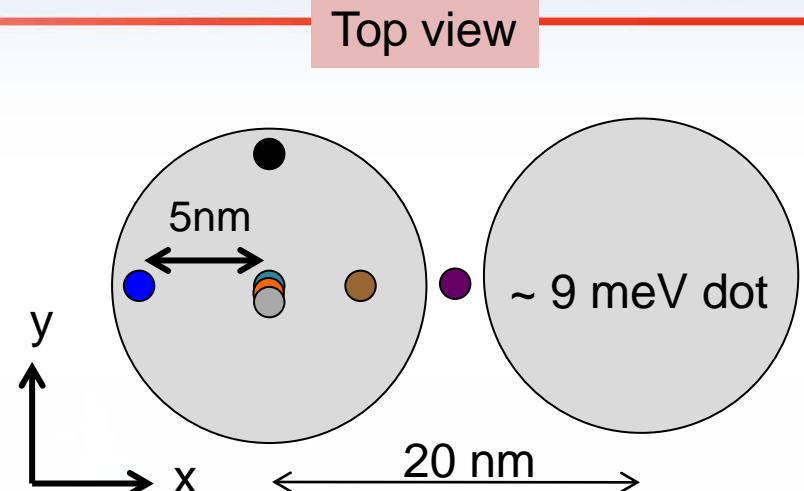
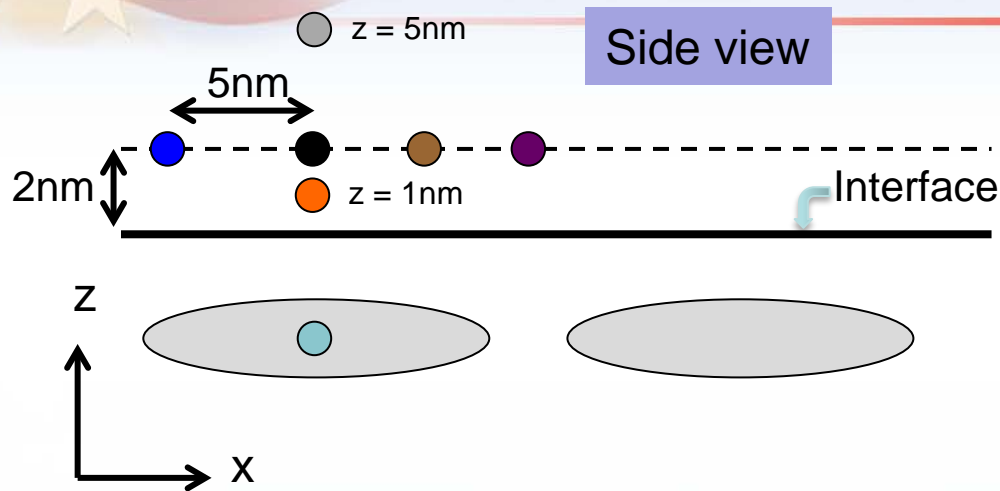
$1 \times 10^{11} \rightarrow 2.5\text{ per QD}$

$1 \times 10^{12} \rightarrow 25\text{ per QD}$

Implications of positive fixed charge



Implications of defects for DQD control



Conclusions:

1. Defect produces offset in detuning
2. Tunnel coupling (slope of curve) can be perturbed
3. Result is statistical variation that will require tuning.
4. Possible challenges to turning off tunneling
5. Valley physics also perturbed

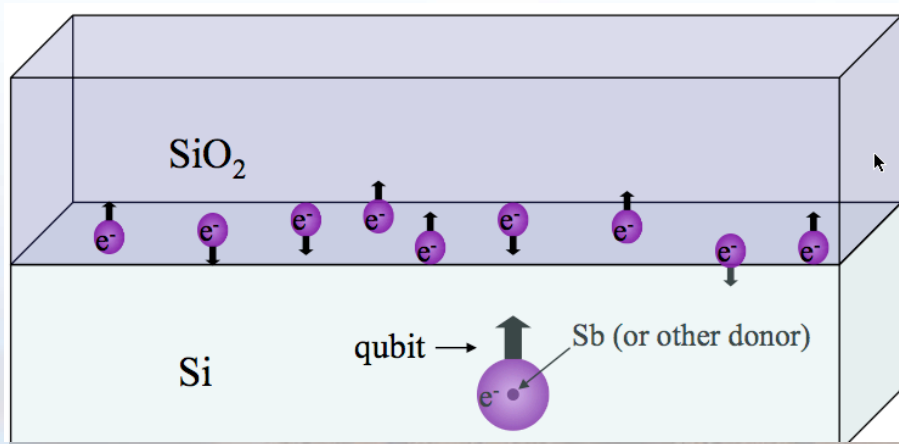
Other considerations: Decoherence near Oxide

Schenkel et al. APL (2004)

Sample	Interface	Peak depth (nm)	T_1 (ms)	T_2 (ms)
120 keV	Si/SiO ₂	50	15±2	0.30±0.03
120 keV	Si—H	50	16±2	0.75±0.04
400 keV	Si/SiO ₂	150	16±1	1.5±0.1
400 keV	Si—H	150	14±1	2.1±0.1

SiO₂ from SNL (2010)

d (nm)	T_2 (SNL SiO ₂)	
25	490 μ s	99.95% ²⁸ Si
100	520 μ s	



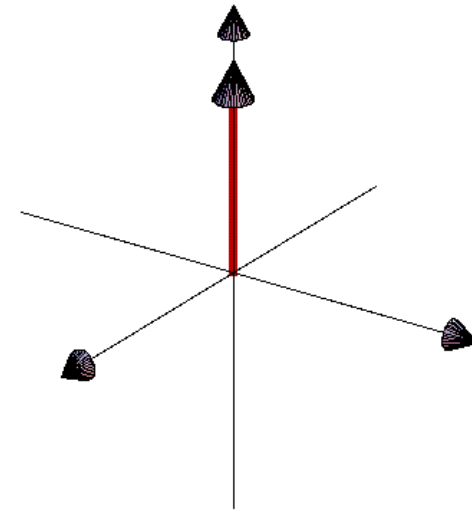
- T_2 not as long as bulk
- Solution: sufficient B-field and low enough temperature?

Doubt: decoherence just not well understood

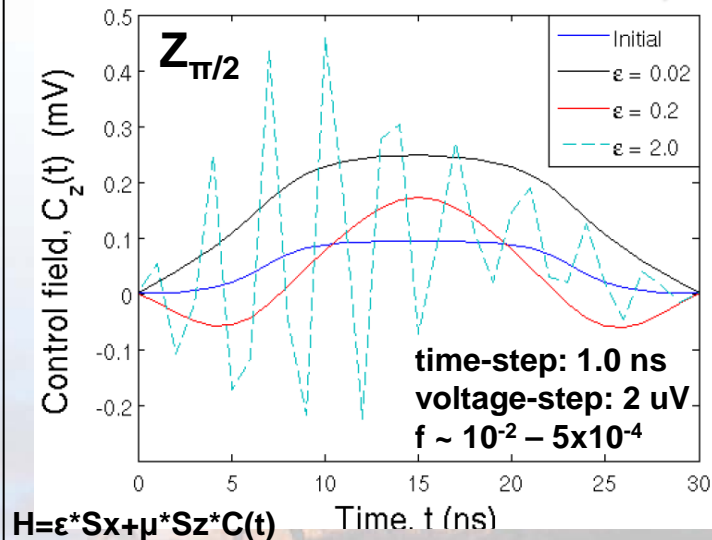
- understand problem
- eliminate decoherence

More robust gates

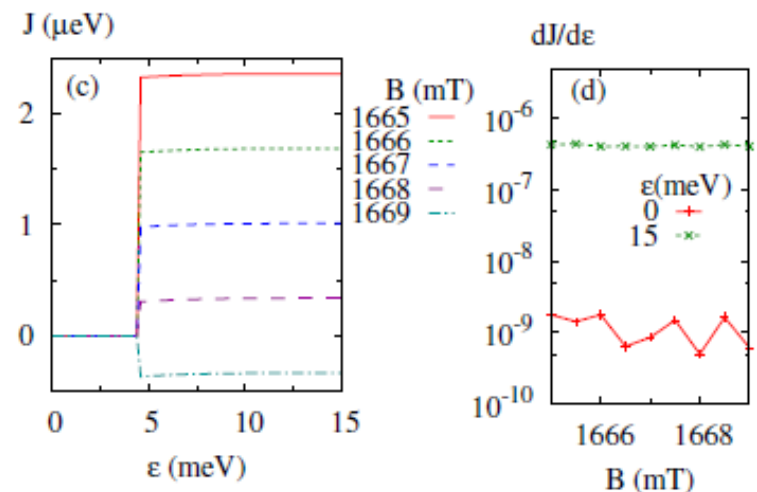
- Voltage fluctuations ($1/f \sim 5 \text{ } \mu\text{eV}$)
 - fidelity of Z gate $\sim [\dots]$
- J-flat proposal to suppress sensitivity to fluctuations
- Slow varying X-rotation during all gates due to background spins
- Hahn-echo and other DD suppresses this kind of error for idle
- Optimal control or DCG suppress X-rotation in the gate itself



Optimal Control Grace et al., arXiv

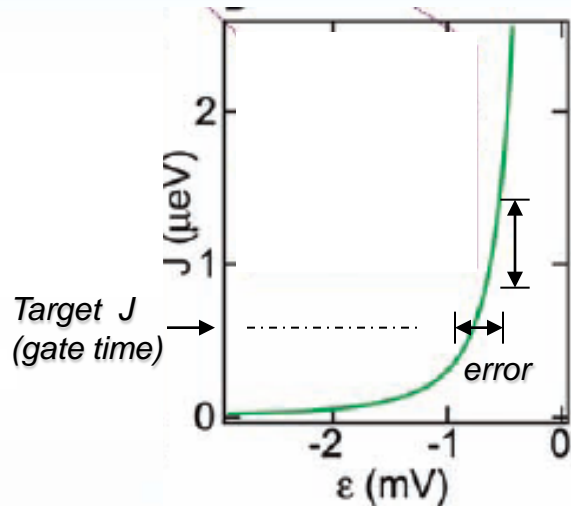


J-flat Nielsen et al., PRB 2010

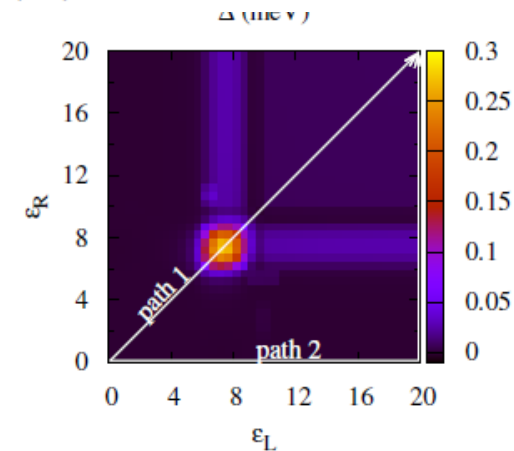
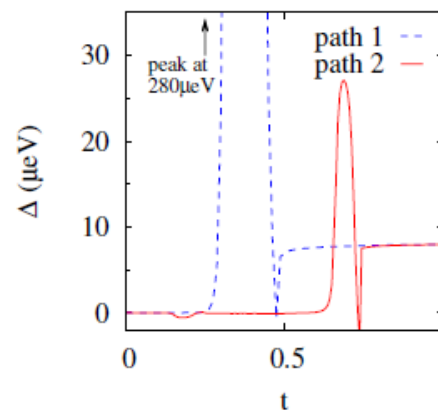
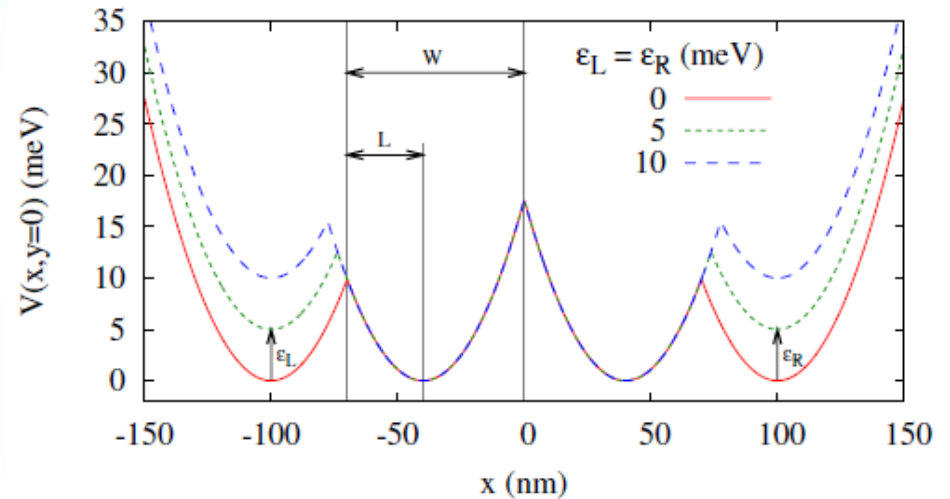


Tuned DQD Potentials for Robust CPHASE-Gate

Petta, Science 2005



Parameters: E_n , L , W , B



- Robust gate design desirable for CPHASE
- Effective mass calculations and CI used
- Robust regions to applied voltage do exist
- μeV coupling energies are predicted when dots are $\sim 60 - 90$ nm separated
- High tunability of QD potential necessary!

Nielsen et al., PRB 82, 075319 (2010)

Nielsen et al., arXiv 1106.1441

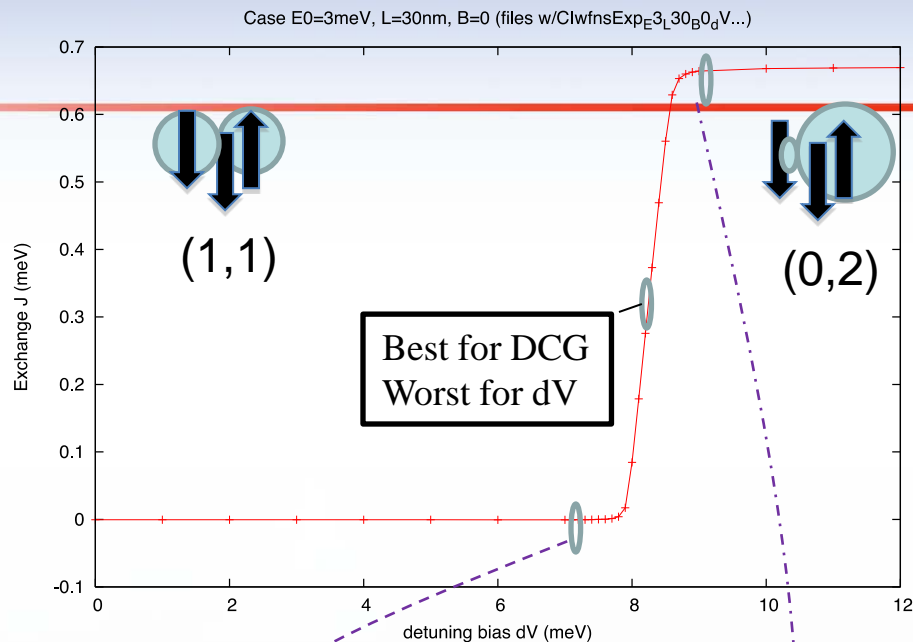


Sandia National Laboratories

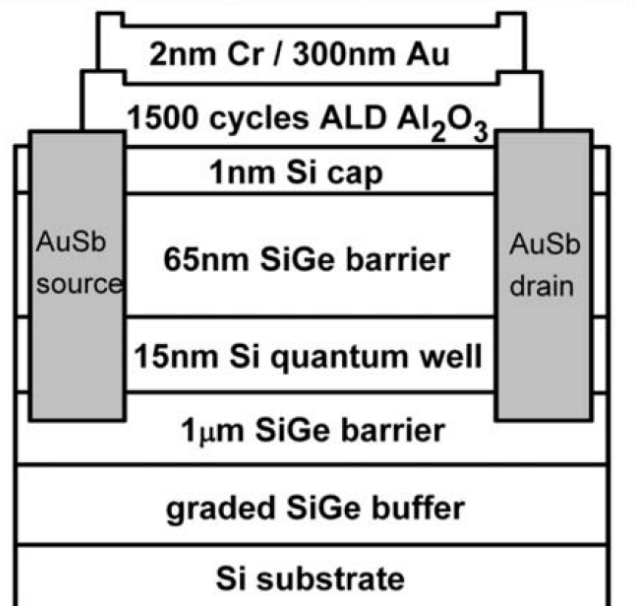
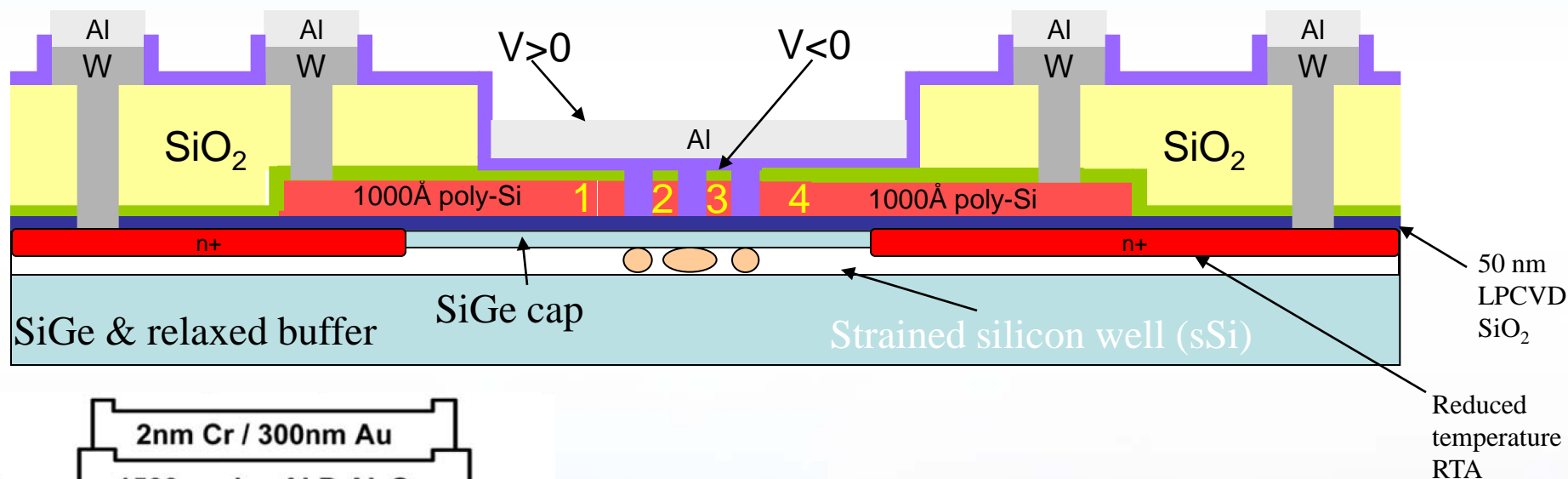
Value of more levels of DD: milestone scope expansion

Observation:

1. X rotation during Z gate due to inhomogeneous field
2. DCG sequence to suppress unknown X rotation could be I-Z-I
3. Correlated noise might not be the same for entire sequence I – Z – I



Enhancement Mode SiGe/sSi: High Mobility & Modular Change to MOS Flow



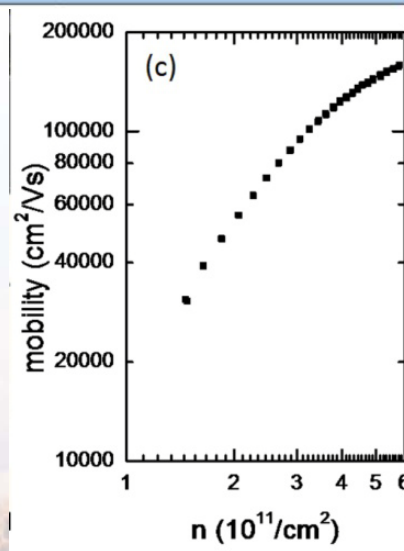
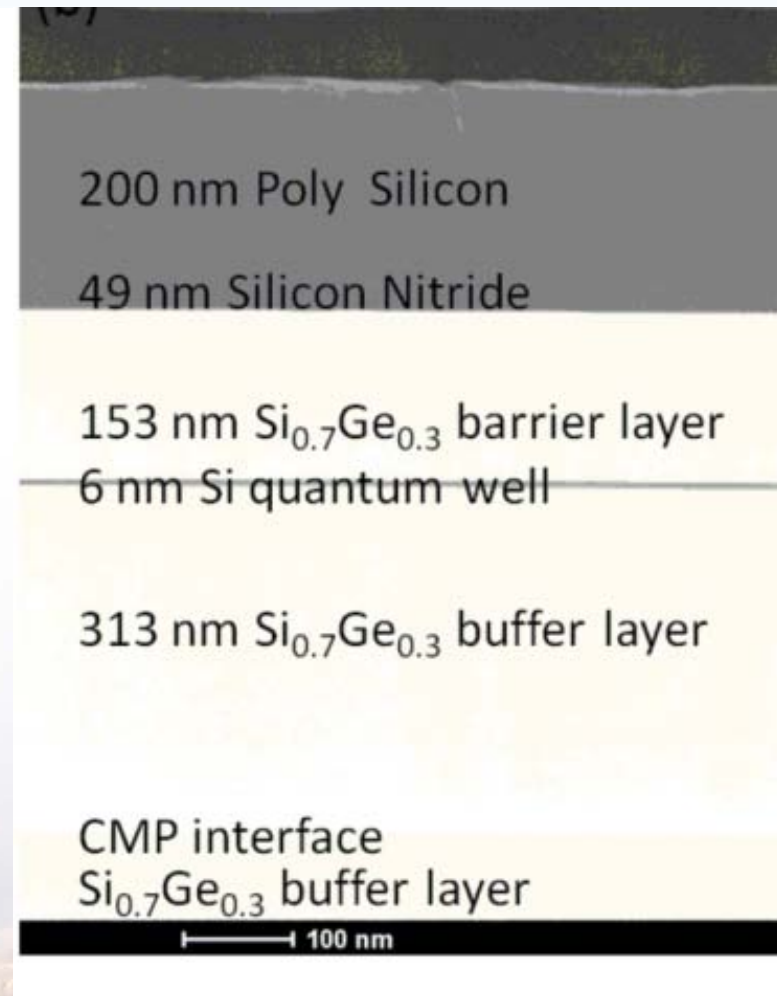
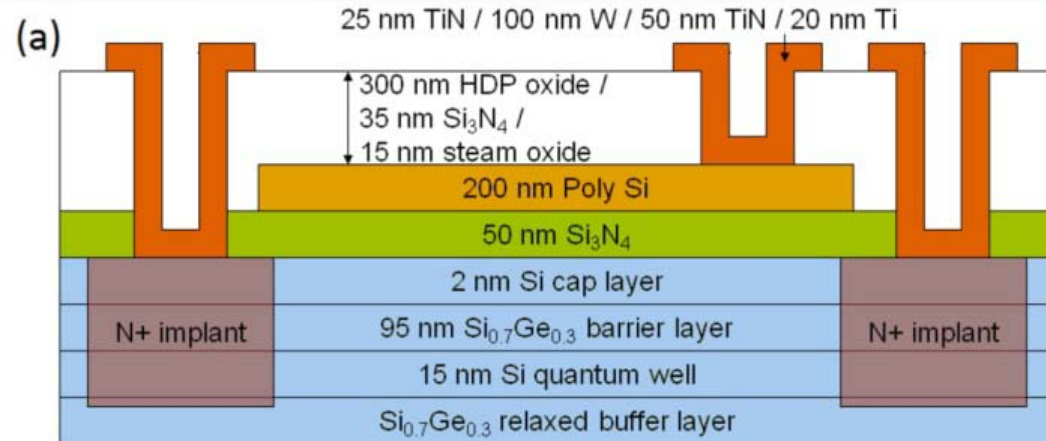
Undoped SiGe Heterostructure

Lu et. al., APL **94**, 182102 (2009)

Mobility $\sim 1.6 \times 10^6$ cm²/Vs

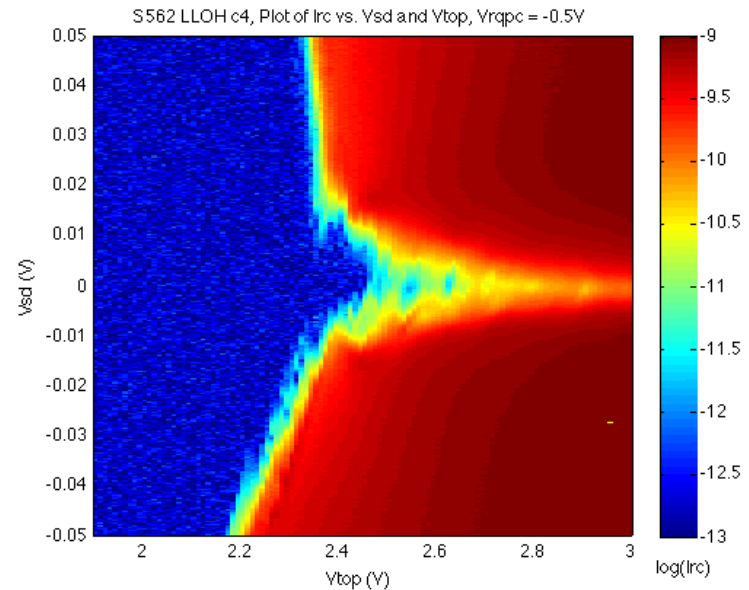
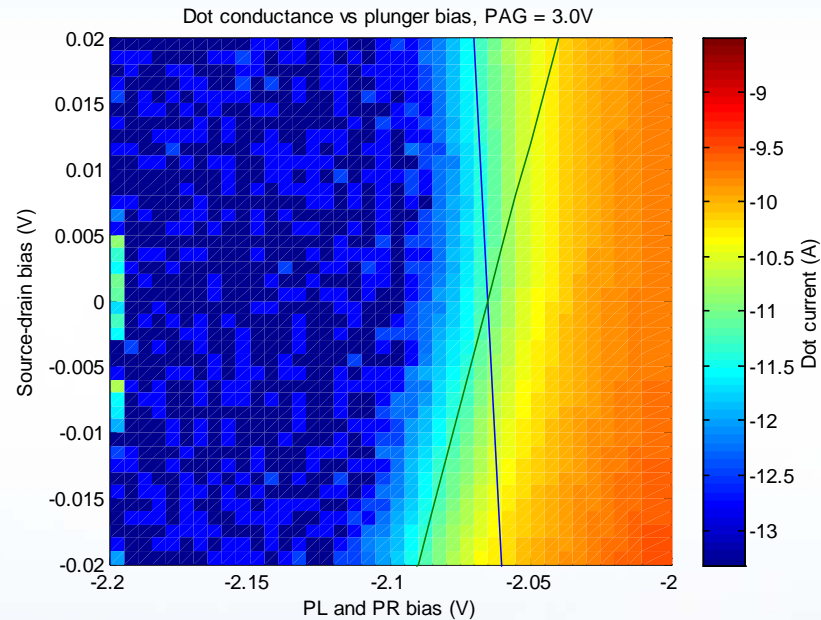
Get the spin away from the surface and defects related to dielectric/crystal interface

Back to the fab: SiGe/sSi



- Modifications:
 1. Substrate
 2. Gate dielectric
 3. Implant & anneals
- Questions:
 1. Ge/Si diffusion
 2. Surface pinning
 3. Mobility

Smooth SiGe barriers at 4K

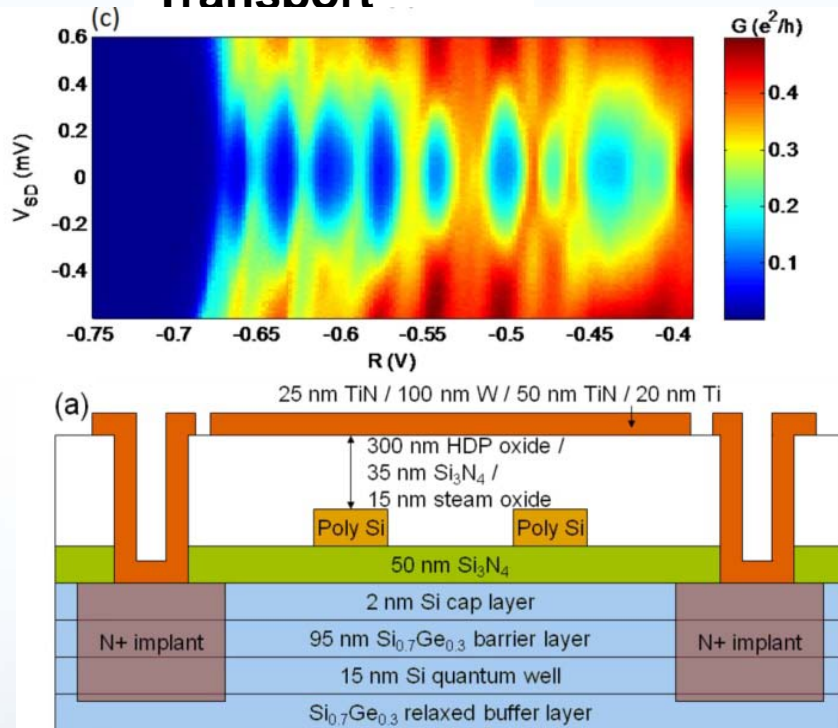


Biggest source of uncertainty is choice of fitting parameter V_0 (point of linear expansion)

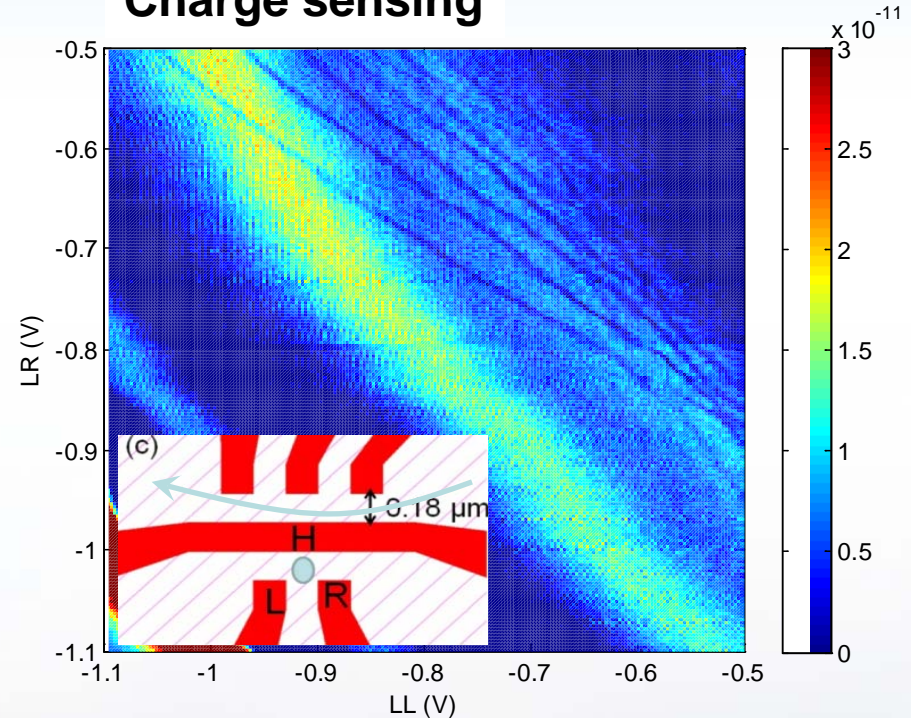
V_{dc} (mV)	Δ (meV)	w (nm)
+20	35 +/- 8	15 +/- 2
+10	34 +/- 8	16 +/- 2
0	35 +/- 8	15 +/- 2
-10	37 +/- 8	13 +/- 1
-20	35 +/- 8	12 +/- 1

Charge sensing: last transition

Transport

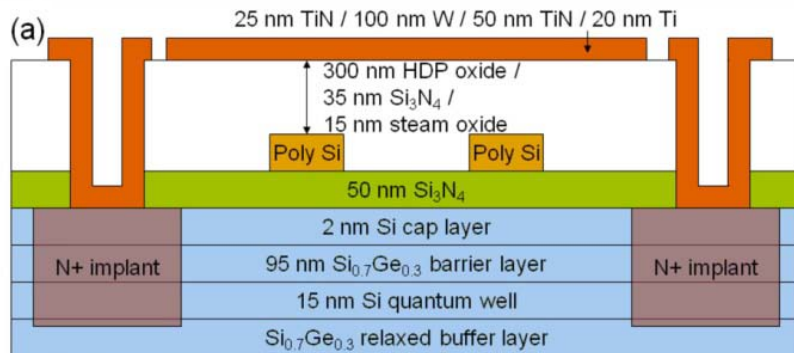
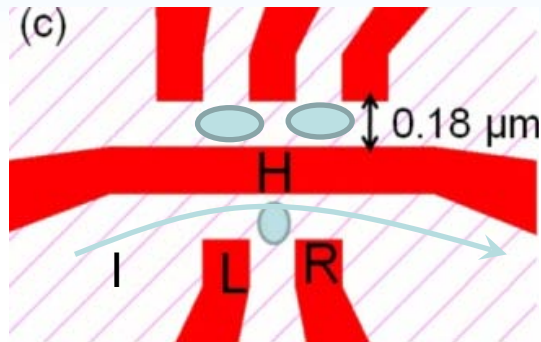


Charge sensing

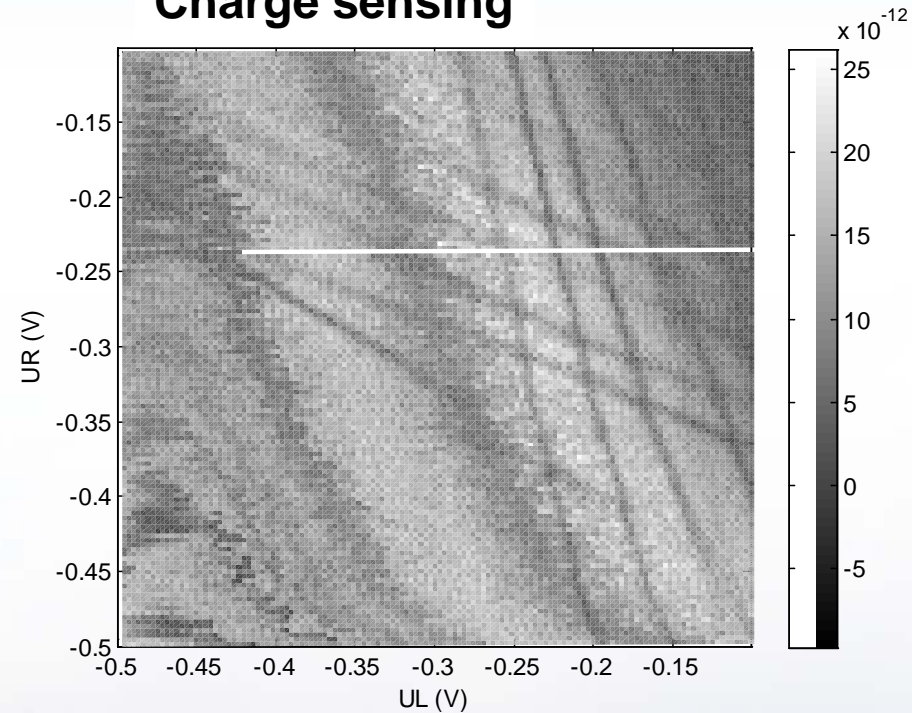


- Opposite channel used as charge sensor
- Last transition in region of high sensitivity of sensor
 - looks like the last electron
- DQD tuning also possible (charge sensed)
- Problem: charge stability

Charge sensing: last transition

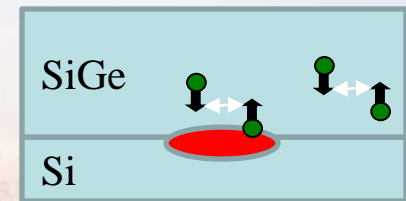
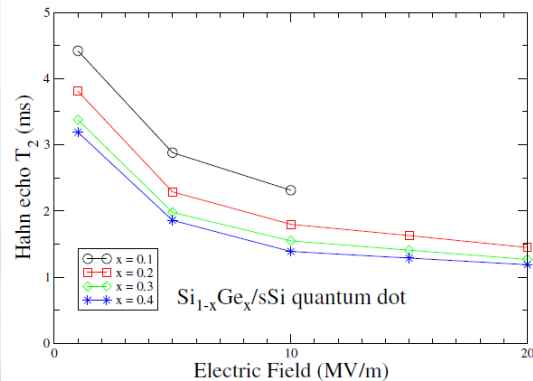
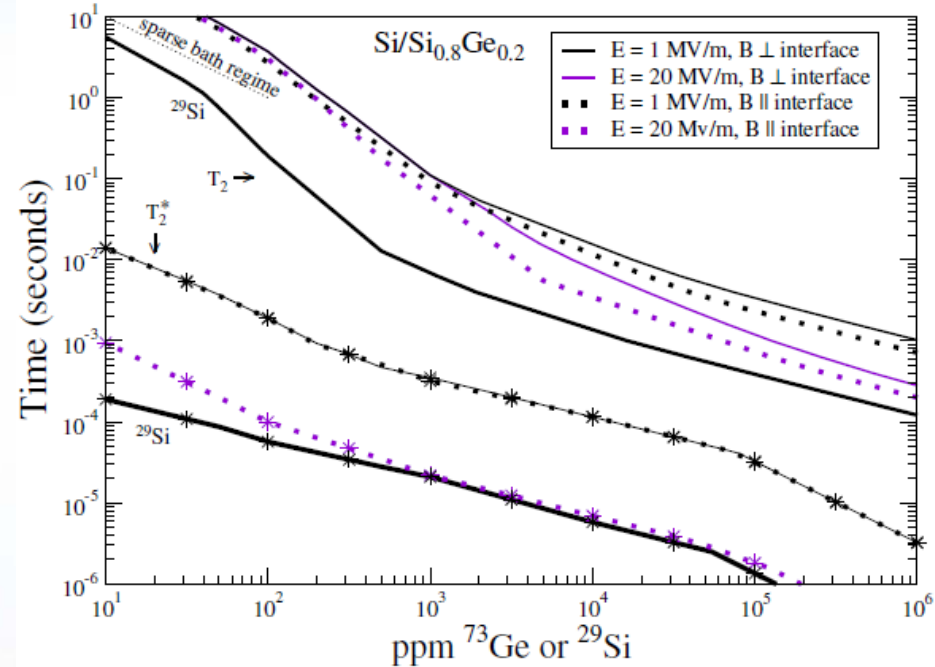
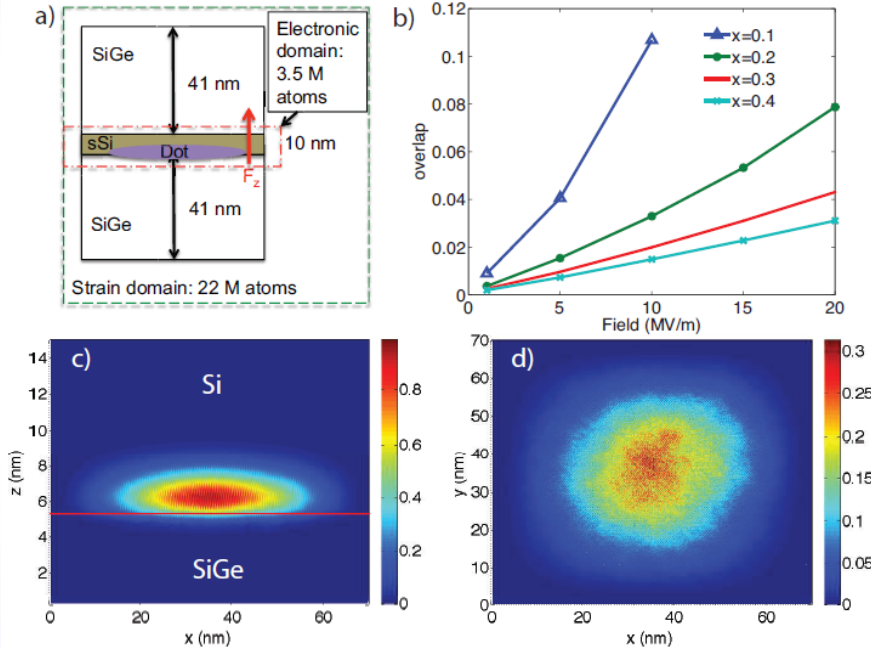


Charge sensing



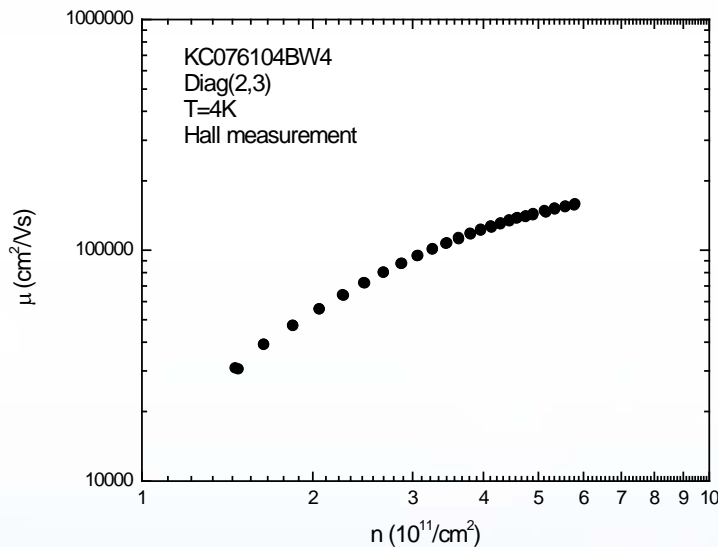
- Double top gated quantum dot w/ DUV lithography
- Relatively regular CB observed w/ small charging energy

Silicon T2 vs. SiGe/sSi (unenriched)

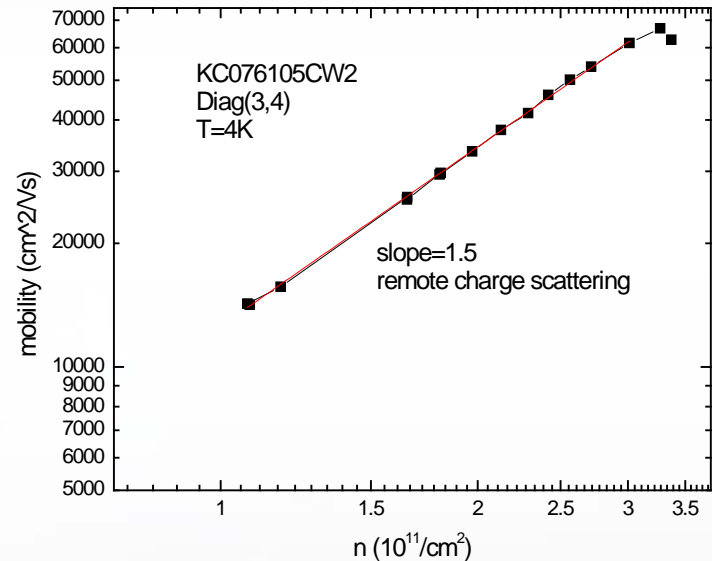


Reduced SiGe barrier thickness for increased stability

150 nm SiGe barrier (not stable)



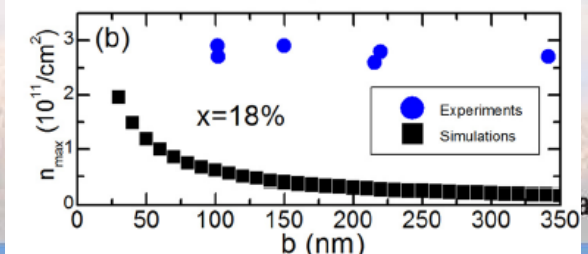
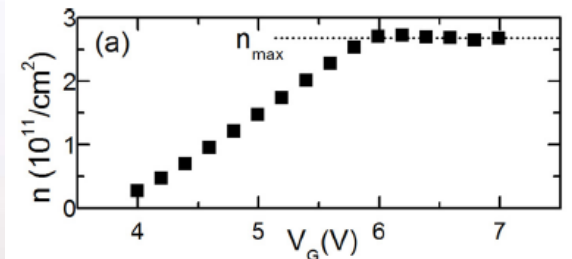
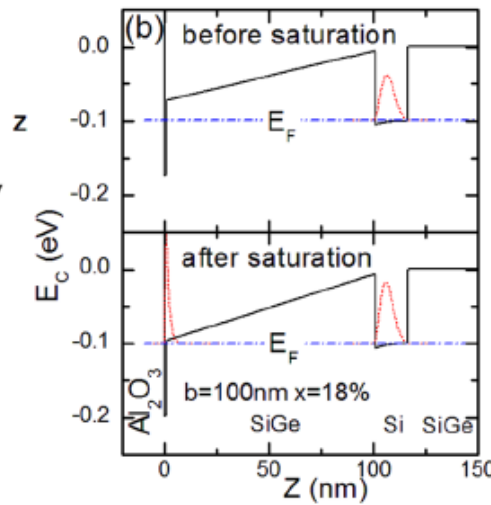
35 nm SiGe barrier (stable)



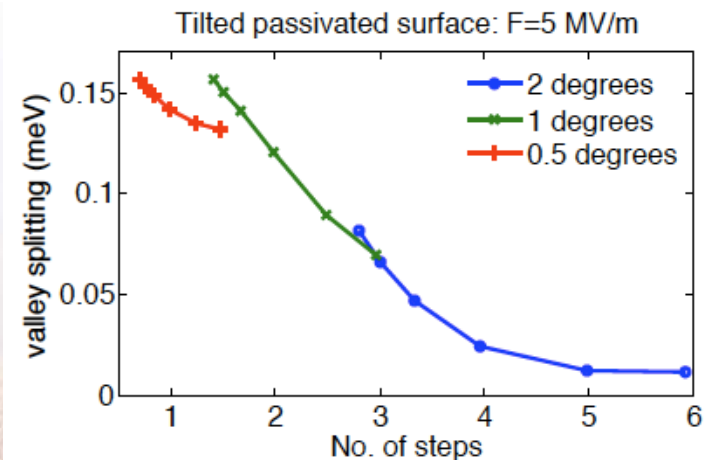
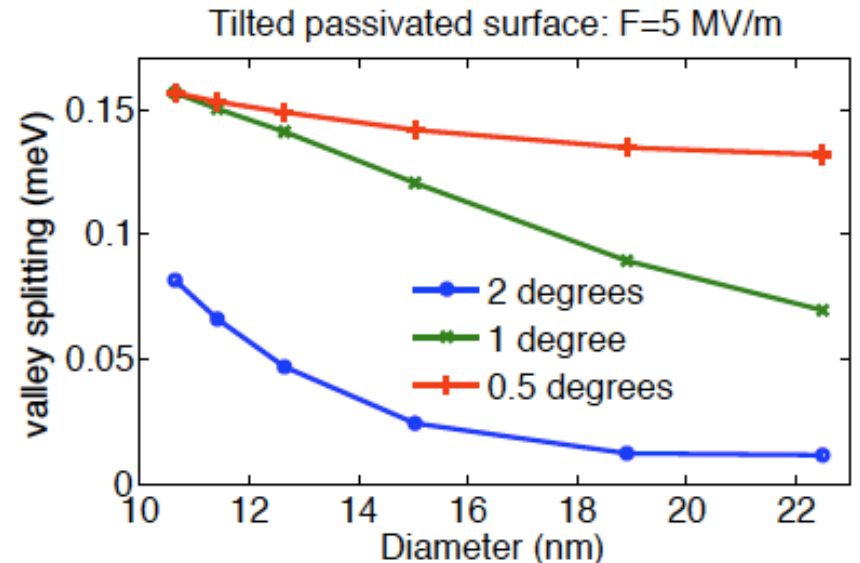
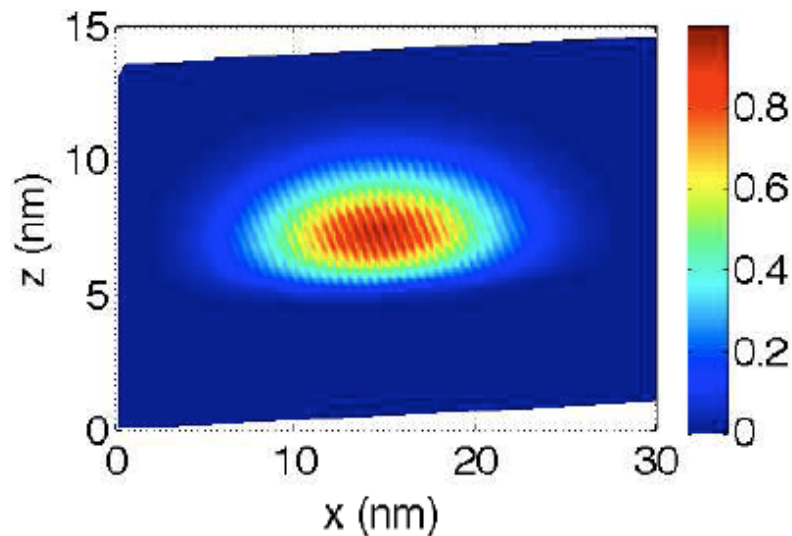
T. Lu, APL 99 (2011)

(a)

Al ₂ O ₃
Si cap, 1 nm
Si _{1-x} Ge _x barrier, b nm
Si quantum well, 15 nm
Si _{1-x} Ge _x relaxed buffer, >1 μm
SiGe graded buffer
Si substrate

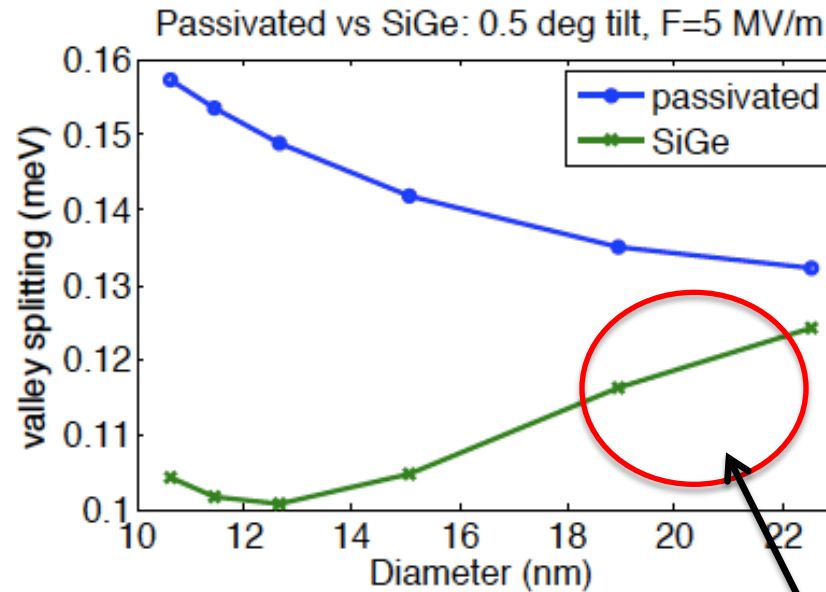


Few electron energies in SiGe



- Modeling of valley splitting at SNL
- Atomistic tight binding calculations (R. Rahman)
- Step edge dependence observed [Friesen et al]
- Calculations done for QD
 - Number of step edges appears to be determining factor

Valley physics still to better understand



Roughness

- Evidence suggests that VS can be big enough
- Ge and Ge profile dependence not well understood
- Big phase space with E-field & processing



Summary

- Measurements and theory suggest very long T2 possible with enrichment and high purity [Witzel et al. PRL 2010]
- Tunable DQDs measured with transport [Tracy et al., APL 2010]
- Transport suggests new MOS design can achieve N=1
 - capacitances are consistent with CAD simulated N=1 capacitances
- Charge sensed MOS DQDs demonstrated
 - Balancing charge sensing, sensitivity and N=2 (DQD) is challenging
- CAD simulation tool being developed and calibrated to assist in design (smaller) and analysis
 - Good tunneling model for CAD needed for design
- Square barrier, WKB tunneling model produces self-consistent results with xpt. fits
- CI/TB calculations indicate positive charge defects can localize the DQD electrons, but tuning can work-around many defects
- J and CPHASE flats are predicted theoretically and are potentially more robust operation points [Nielsen et al., PRB and arXiv]
- T2 at surface near oxides is still not well established
- DCG might be inconsistent with J flat
- SiGe enhancement mode quantum dots have been developed (just get away from defects)
 - Measurements are consistent with charge sensed few electron QD and DQDs [Lu et al., APL 2011]
 - Barriers look cleaner
 - Sudden shut-off in 150K mobility material, thinner SiGe barrier, 70K mobility, has fewer abrupt shut-offs
 - Ge isotopes are predicted to limit T2 [Witzel et al., submitted PRB rapid]





Acknowledgements

- The technical teams

Silicon quantum dot: M. Lilly, N. Bishop, S. Carr, T.-Z. Lu, L. Tracy, K. Nguyen, T. Pluym, J. Dominguez, J. Wendt, J. Stevens, B. Silva, E. Bower, R. Gillen

Donor and donor-dot: E. Bielejec, E. Bussmann, D. Perry, B. McWatters, A. MacDonald

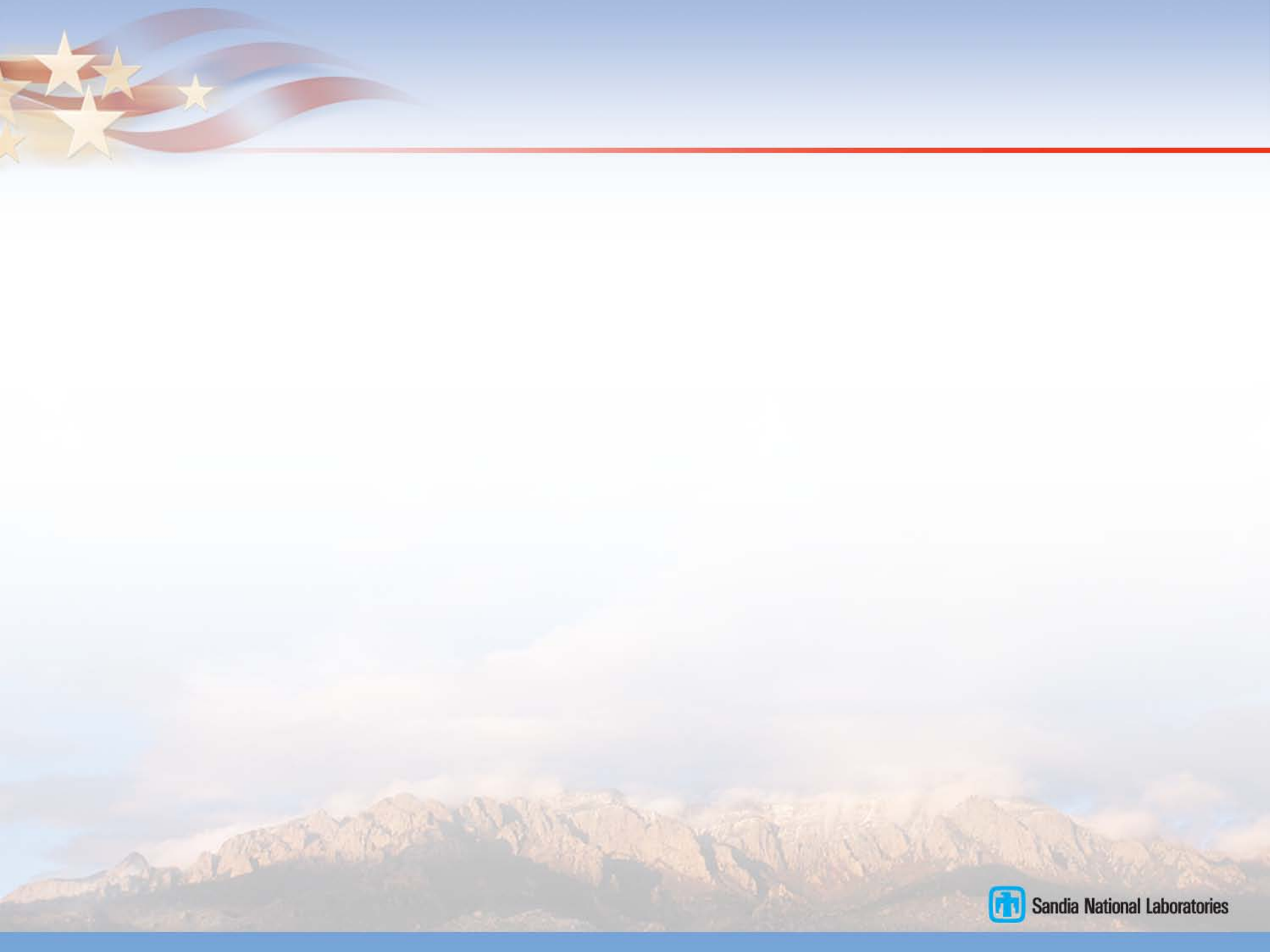
Device modeling: R. Muller, R. Young, W. Witzel, E. Nielsen, R. Rahman, K. Young, J. Verley

Cryogenic electronics: T. Gurrieri, J. Levy, R. Young, J. Hamlet, K. Barkley

Architecture and quantum error correction: A. Ganti, M. Grace, W. Witzel, U. Onunkwo, A. Landahl, C. Phillips, R. Carr, T. Tarman

- Joint research efforts with external community:

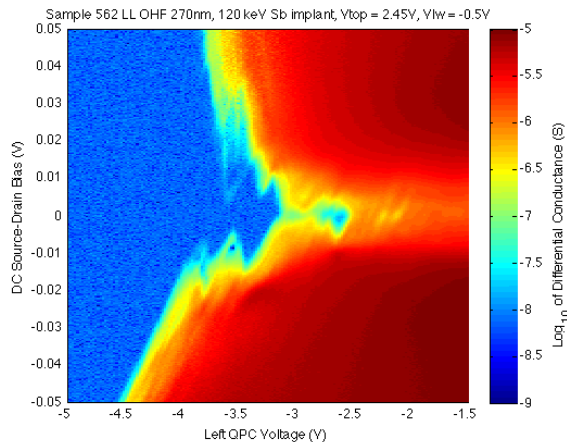
- U. Wisconsin (M. Eriksson, D. Savage, M. Friesen, R. Joynt)
- Australian Centre for Quantum computing Technology (L. Hollenberg, D. Jamieson, M. Simmons, A. Dzurak, A. Morello)
- Princeton University (S. Lyon)
- NIST (N. Zimmerman)
- U. Maryland (S. Das Sarma, M. Peckerar)
- Lawrence Berkeley National Labs (T. Schenkel)
- National Research Council (A. Sachrajda)
- U. Sherbrooke (M. Pioro-Ladriere)



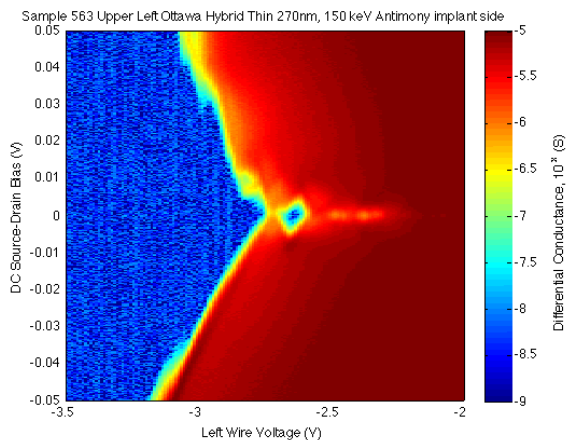
Statistical analysis of implanted tunnel barriers

Implant

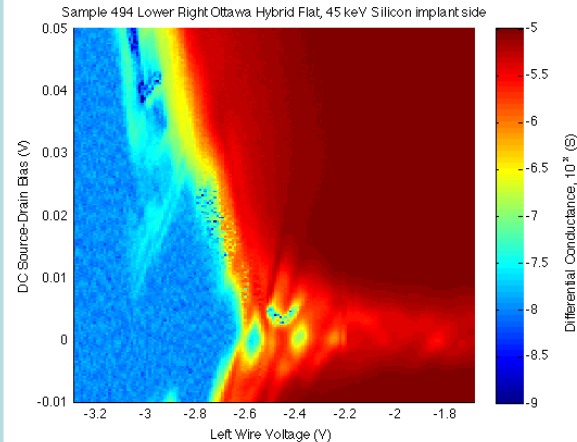
120 keV Sb implant



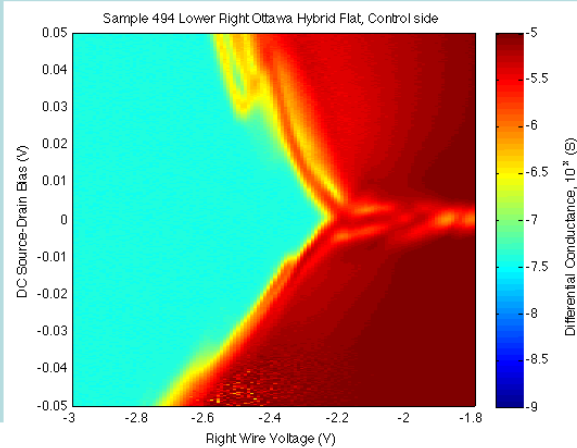
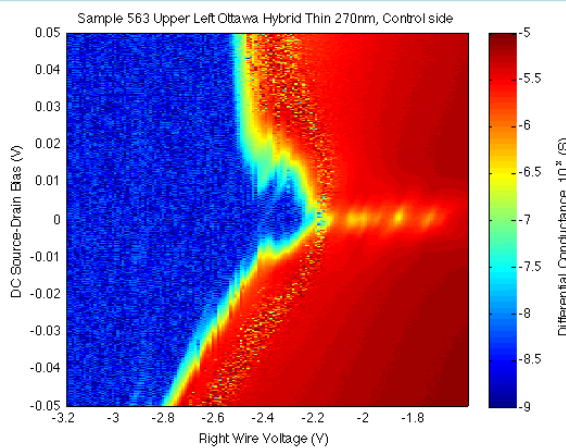
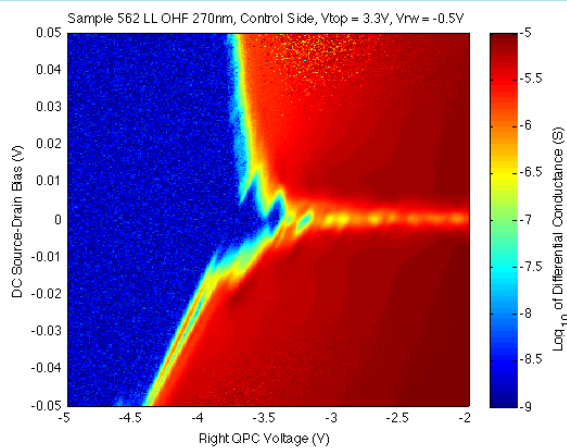
150 keV Sb implant



45 keV Si implant

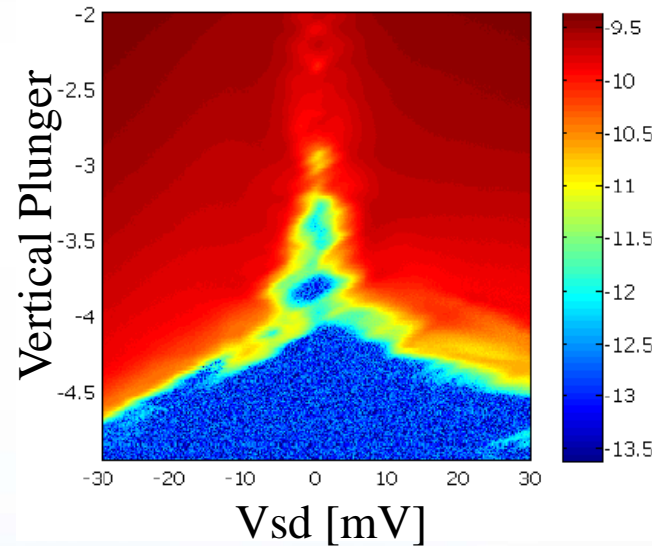
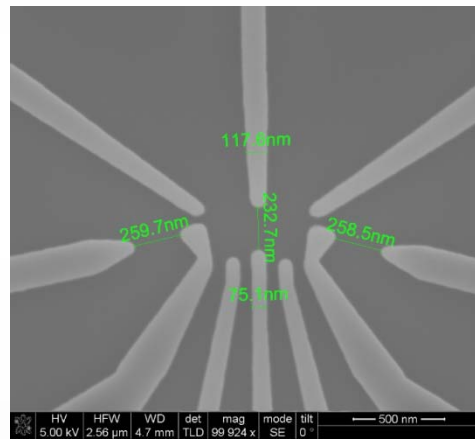


Control

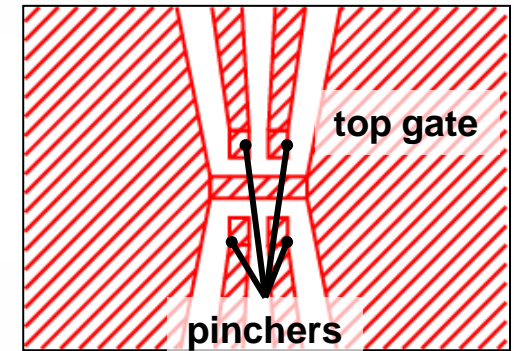


Donor signature difficult to find, but very useful for modeling tunnel barrier.

Qualitative differences between disorder in different structures



- Common in MOS for charging energy to rapidly increase as $N \Rightarrow 1$
- Charge sensing also detects outlier(s)
- Large area devices produce small dot charging energies?



(K. Eng & L. Tracy)

$V_{tg} = 4$ V
 $W_g = -75$ V
 $T = 0.25$ K

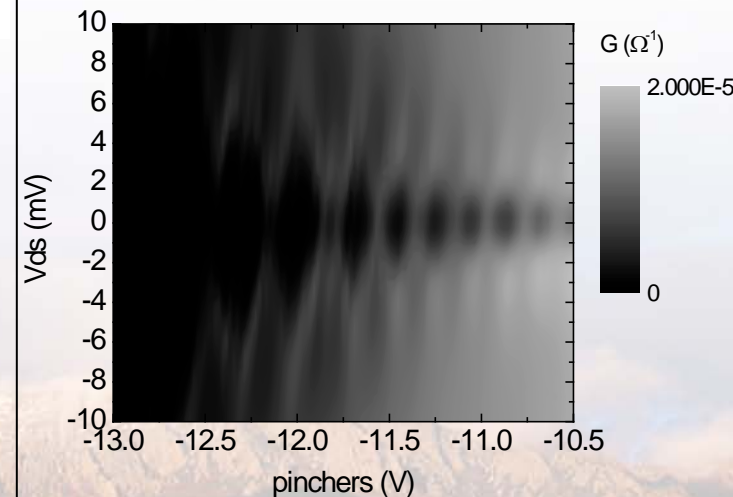
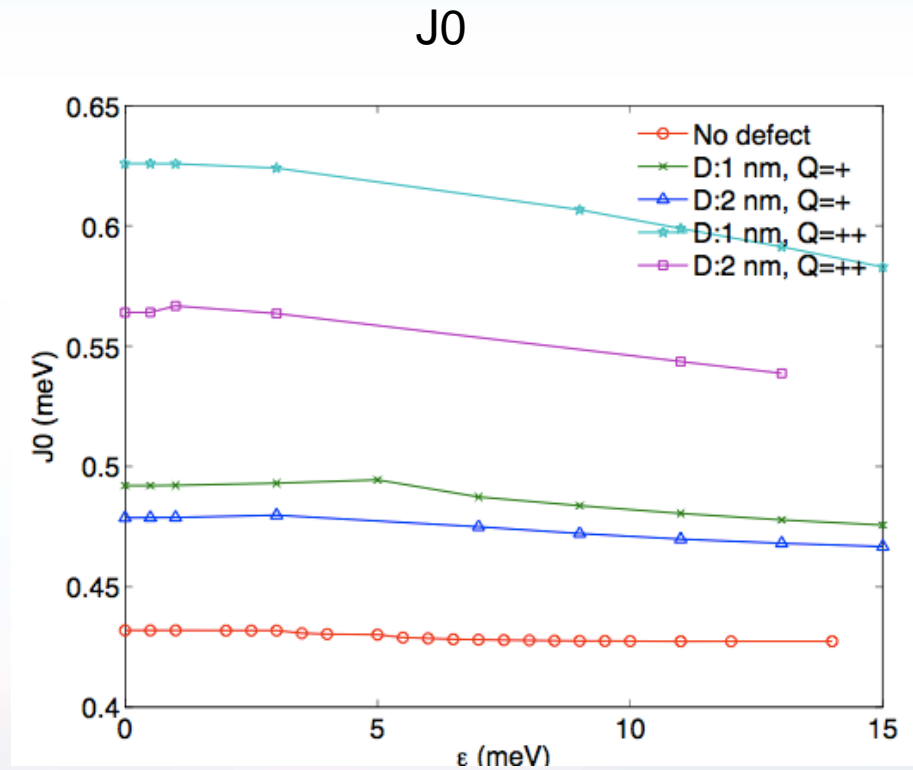
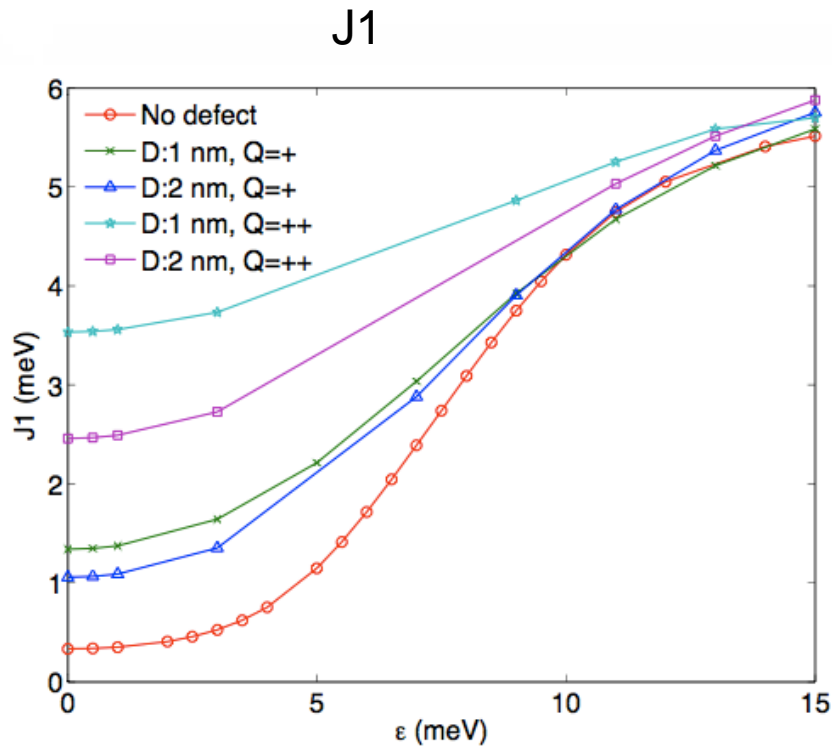
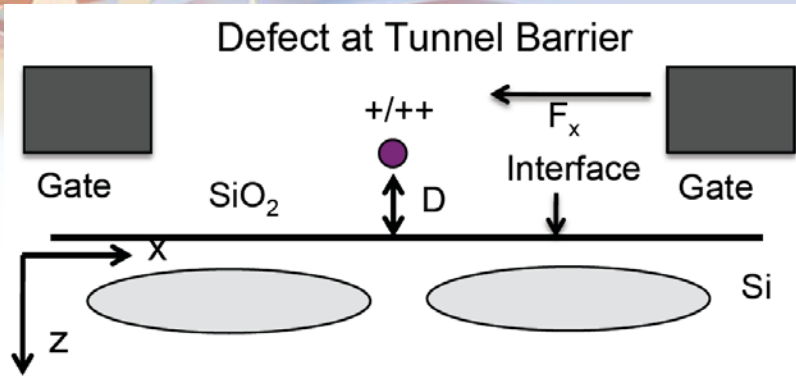
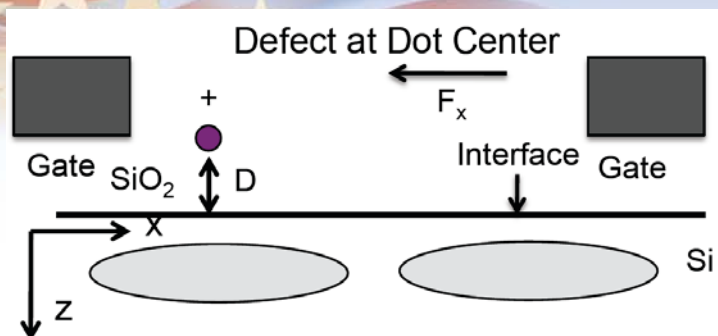


Fig. 3a) Defect at Tunnel barrier

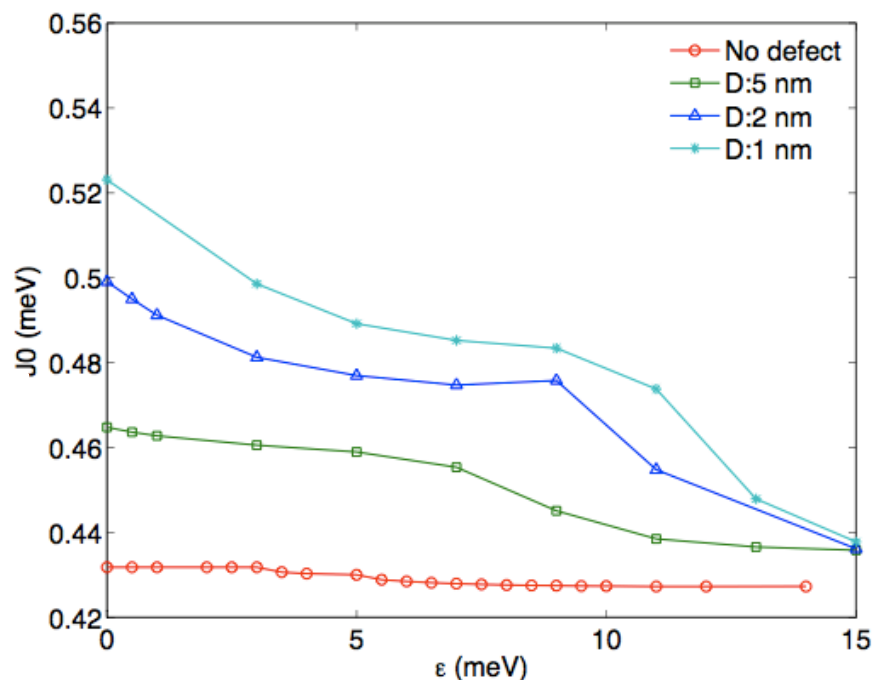


Stronger the effect of the defect potential, the greater is the valley splitting, hence the curves move up

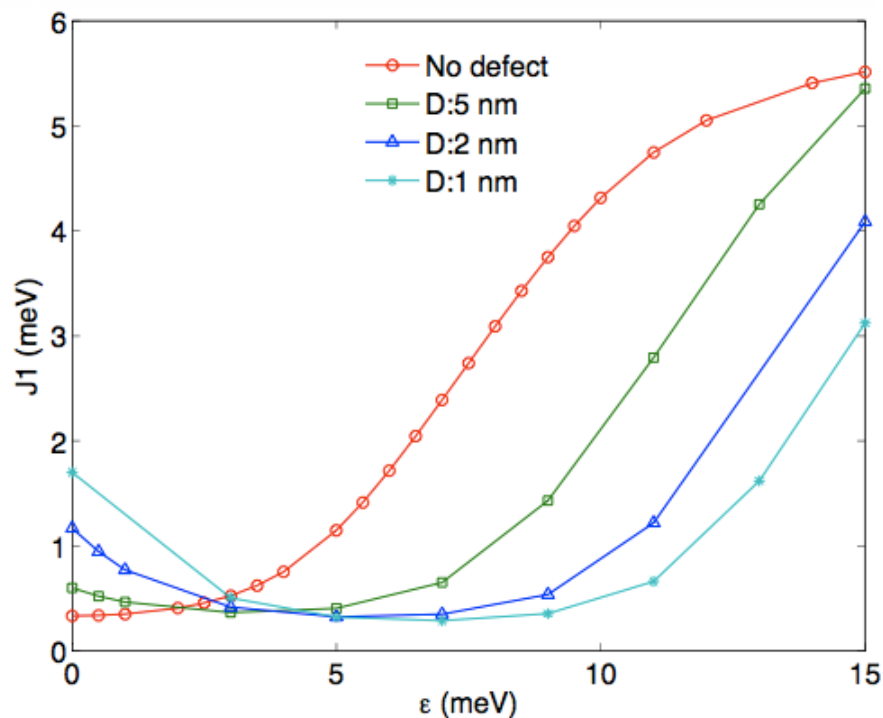
Fig. 3b) Defect at center of one dot



J0

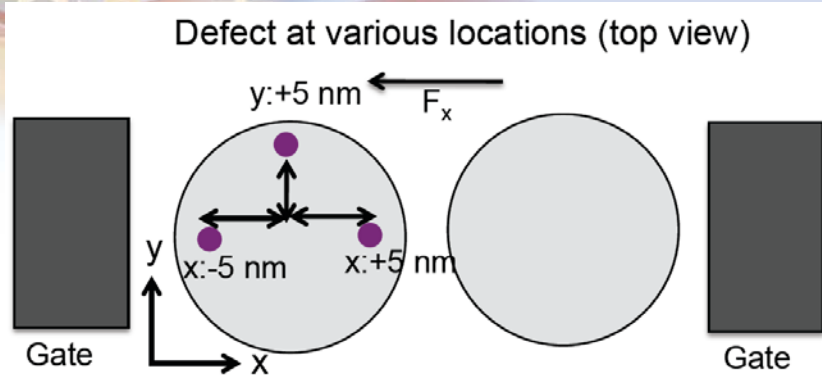


J1

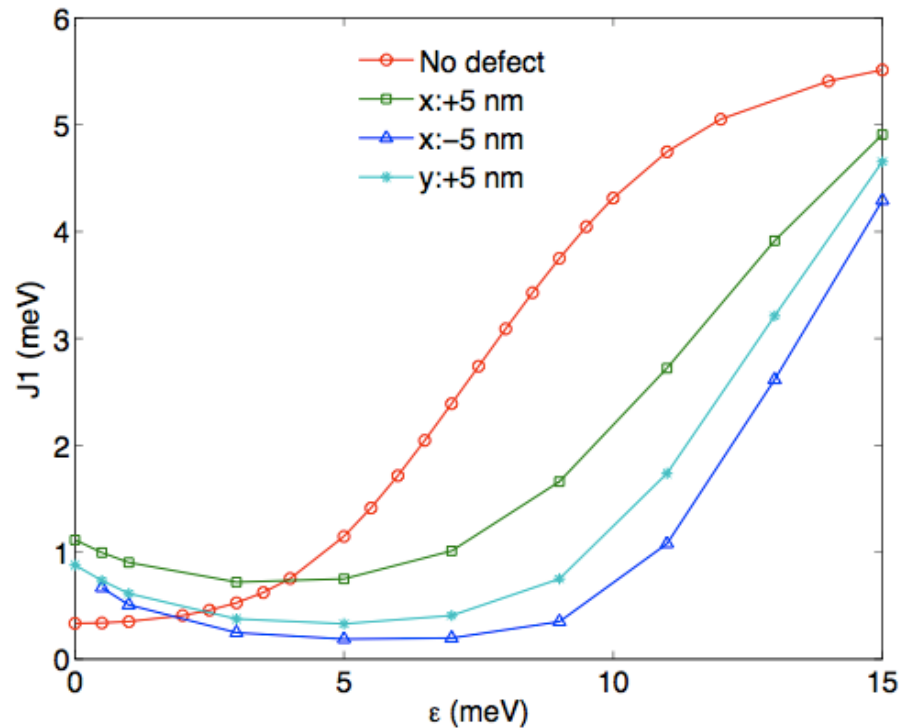


Defect cause VS to be different in two dots, hence the slope of the curve. The “hump” is a bit mysterious and doesn’t seem to be a numerical artifact.

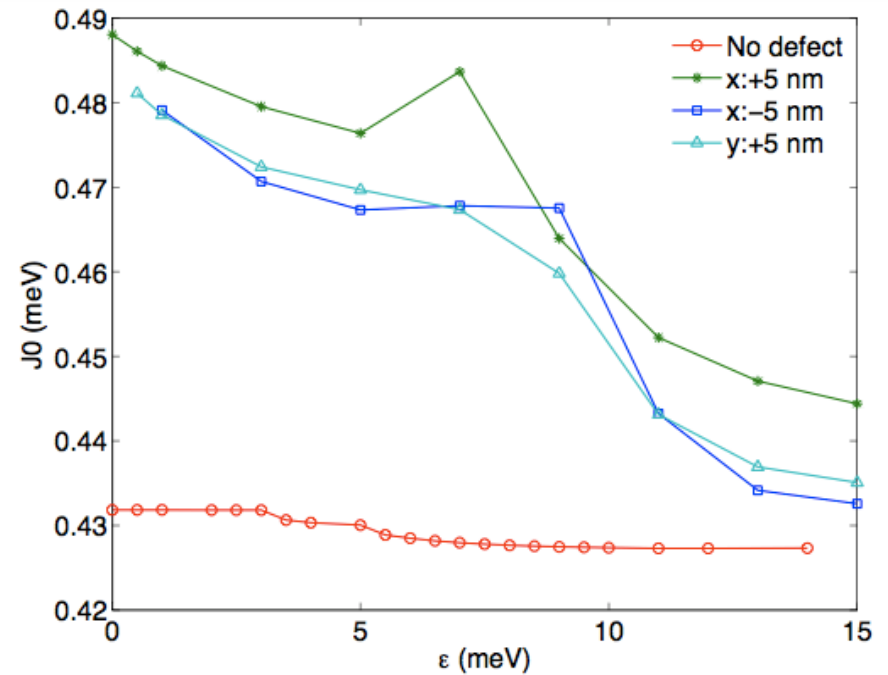
Fig. 3c) Defect at various locations



J1



J0



Same effect: Asymmetric VS